1. Overview

1.1 Features

The R8C/38T-A Group of single-chip microcontrollers (MCUs) incorporates the R8C CPU core, which provides sophisticated instructions for a high level of efficiency. With 1 Mbyte of address space, the CPU core is capable of executing instructions at high speed. In addition, it features a multiplier for high-speed arithmetic processing.
Power consumption is low, and additional power control is possible by selecting the operating mode. The R8C/38T-A Group is also designed to maximize EMI/EMS performance.
Integration of many peripheral functions, including multifunction timer and serial interface on the same chip, reduces the number of system components.
The R8C/38T-A Group integrates a touch sensor control unit, which enables detection of the floating capacitance of the electrostatic capacitive touch electrode.
This group also has on-chip data flash (1 KB × 4 blocks) with background operation (BGO) function.

1.1.1 Applications

Electronic household appliances, office equipment, audio equipment, consumer equipment, etc.

1.1.2 Specifications

Tables 1.1 and 1.2 outline Specifications.

Table 1.1 Specifications (1)

Item	Function	Description
CPU	Central processing unit	R8C CPU core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns (CPU clock = 20 MHz, VCC = 2.7 V to 5.5 V) 200 ns (CPU clock = 5 MHz, VCC = 1.8 V to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operating mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM, data flash	Refer to **Table 1.3 Product List**.
Voltage detection	Voltage detection circuit	• Power-on reset • Voltage detection with three check points (the detection levels for voltage detection 0 and voltage detection 1 can be selected.)
I/O ports	Programmable I/O ports	• Input only: 1 • CMOS I/O: 75, selectable pull-up resistor • High current drive ports: 75
Clock	Clock generation circuits	• 4 circuits: XIN clock oscillation circuit, XCIN clock oscillation circuit, high-speed on-chip oscillator (with frequency adjustment function), low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Divided by 1, 2, 4, 8, or 16 can be selected • Low-power mode: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
Interrupts		• Number of interrupt vectors: 69 • External interrupt inputs: 9 (INT × 5, key input × 4) • Priority levels: 7
Event link controller (ELC)		• Events output from peripheral functions can be linked to events input to different peripheral functions. (30 sources × 10 types of event link operations) • Events can be handled independently from interrupt requests.
Watchdog timer		• 14 bits × 1 • Selectable reset start function • Selectable low-speed on-chip oscillator for the watchdog timer
DTC (data transfer controller)		• 1 channel • Activation sources: 27 • Transfer modes: 2 (normal mode, repeat mode)
Timer	Timers RJ_0	16 bits × 1: 1 circuit integrated on-chip Timer mode (periodic timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB2_0	16 bits × 1: 1 circuit integrated on-chip Timer mode (periodic timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timers RC_0	16 bits (with 4 capture/compare registers) × 1: 1 circuit integrated on-chip Timer mode (input capture function, output compare function), PWM mode (output: 3 pins), PWM2 mode (PWM output: 1 pin)
	Timer RE2	8 bits × 1 Compare match timer mode, real-time clock mode

Table 1.2 Specifications (2)

Item	Function	Description
Serial interface	UART0_0 and UART0_1	2 channels Clock synchronous serial I/O mode, clock asynchronous serial I/O mode
	UART2	1 channel Clock synchronous serial I/O mode, clock asynchronous serial I/O mode, I^2C mode (I^2C-bus), multiprocessor communication mode
Clock Synchronous serial interface	(SSU) SSU_0	1 channel (also used for the I^2C bus)
	(I^2C bus) I^2C_0	1 channel (also used for the SSU)
LIN module	HW-LIN_0	Hardware LIN 1 channel (timer RJ_0, UART0_0, or UART0_1 used)
A/D converter		Resolution: 10 bits × 20 channels, sample and hold function, sweep mode
Comparator B		2 circuits
Touch sensor control unit (TSCU)		System CH × 4, electrostatic capacitive touch detection × 36
CRC calculator		CRC-CCITT ($X^{16} + X^{12} + X^5 + 1$), CRC-16 ($X^{16} + X^{15} + X^2 + 1$) compliant
Flash memory		• Program/erase voltage: VCC = 2.7 V to 5.5 V • Program/erase endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function • BGO (background operation) function (data flash)
Operating frequency/ Power supply voltage		CPU clock = 20 MHz (VCC = 2.7 V to 5.5 V) CPU clock = 5 MHz (VCC = 1.8 V to 5.5 V)
Current consumption		Typ. 6.5 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 4.0 μA (VCC = 3.0 V, wait mode f(XCIN) = 32 kHz) Typ. 2.2 μA (VCC = 3.0 V, stop mode)
Operating ambient temperature		-20°C to 85°C (N version) -40°C to 85°C (D version) (1)
Package		80-pin LQFP Package code: PLQP0080KB-A (previous code: 80P6Q-A)

Note:
1. Specify the D version if it is to be used.

1.2 Product List

Table 1.3 lists product information. Figure 1.1 shows the Product Part Number Structure.

Table 1.3 Product List **Current of Dec 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F21388SNFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080KB-A	N version
R5F2138ASNFP	96 Kbytes		8 Kbytes		
R5F2138CSNFP	128 Kbytes		10 Kbytes		
R5F21388SDFP	64 Kbytes		6 Kbytes	PLQP0080KB-A	D version
R5F2138ASDFP	96 Kbytes		8 Kbytes		
R5F2138CSDFP	128 Kbytes		10 Kbytes		

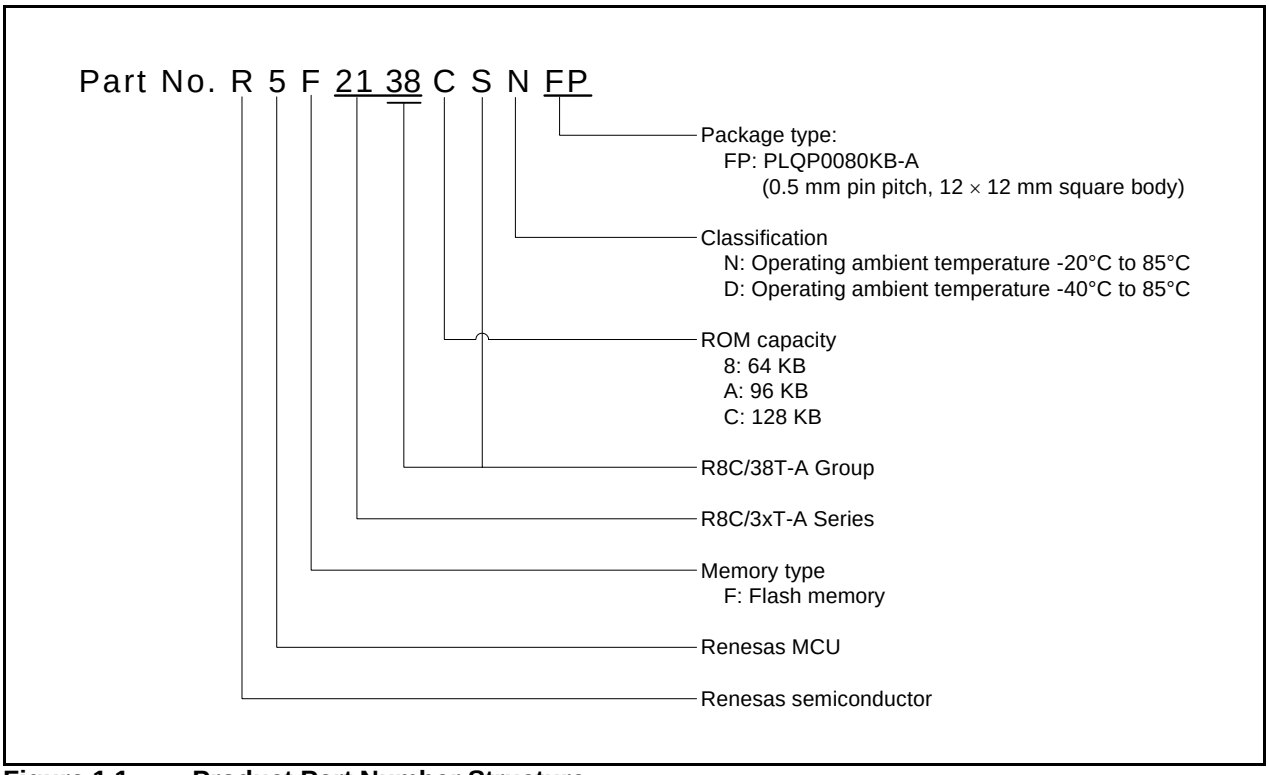


Figure 1.1 Product Part Number Structure

1.3 Block Diagram

Figure 1.2 shows the Block Diagram.

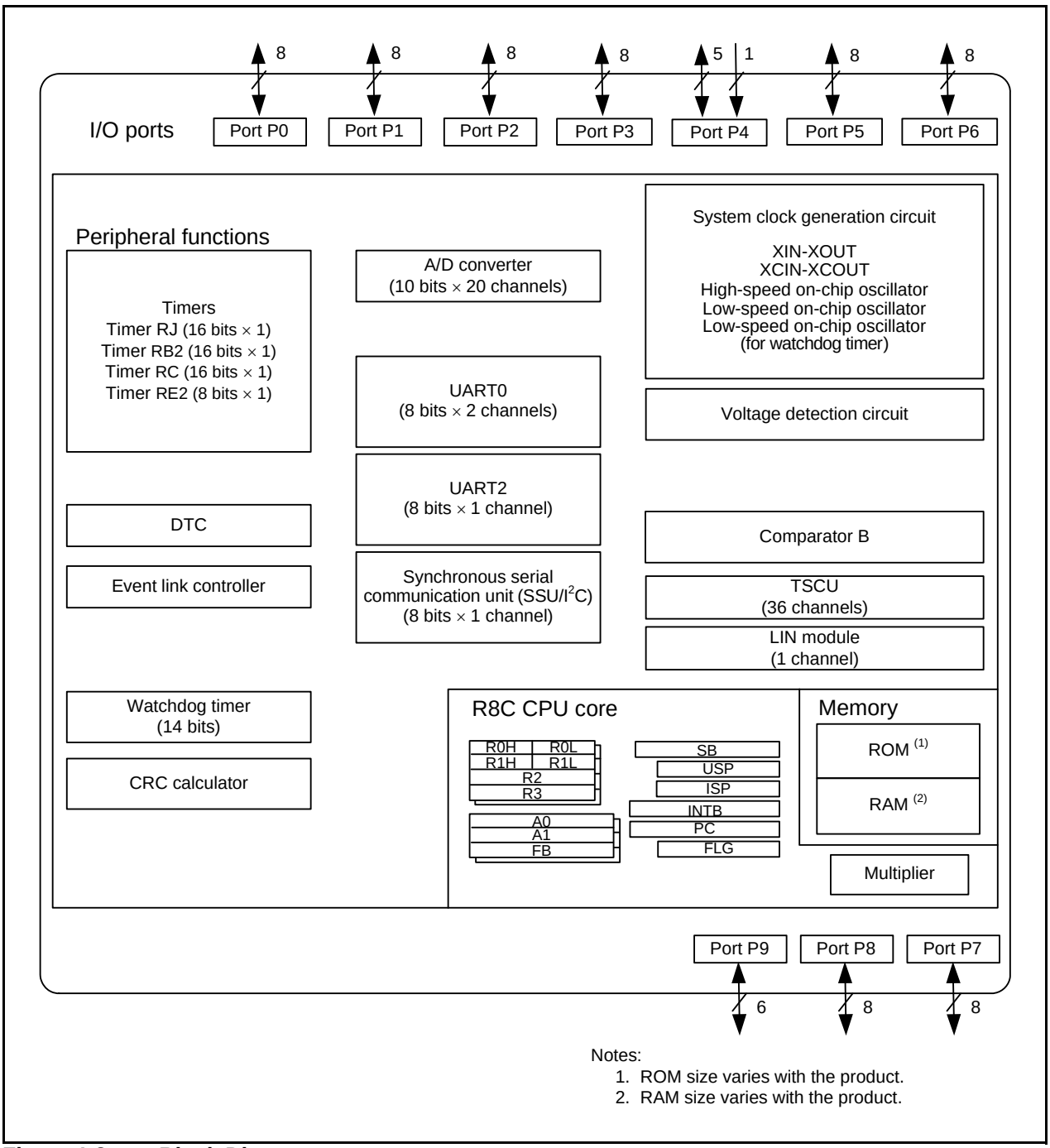


Figure 1.2 Block Diagram

1.4 Pin Assignment

Figure 1.3 shows Pin Assignment (Top View). Tables 1.4 to 1.9 list the Pin Name Information by Pin Number.

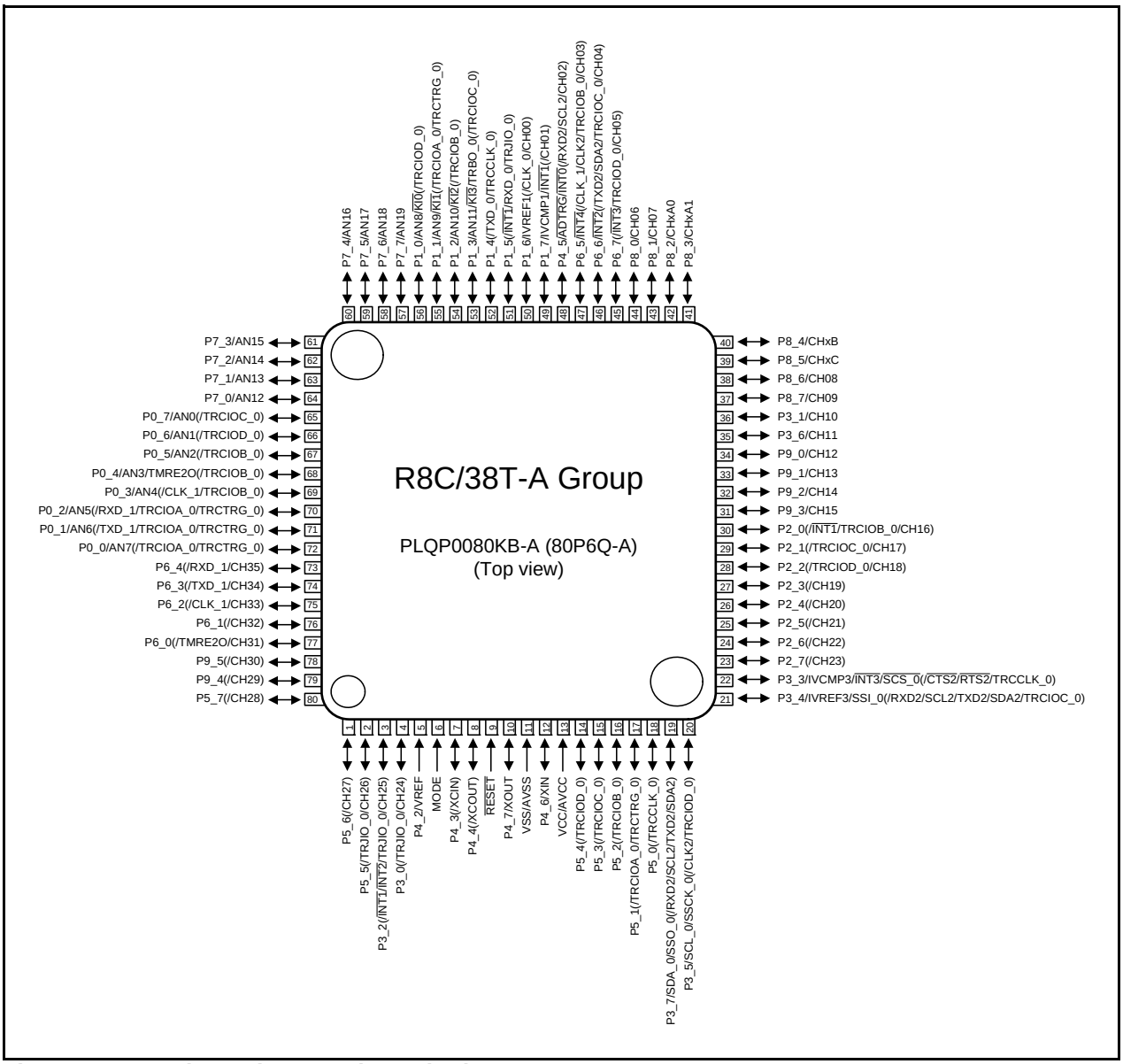


Figure 1.3 Pin Assignment (Top View)

Table 1.4 Pin Name Information by Pin Number (INT, URAT0, and UART2) (1)

Port	Pin No.	INT					UART0						UART2						
		$\overline{INT0}$	$\overline{INT1}$	$\overline{INT2}$	$\overline{INT3}$	$\overline{INT4}$	TXD_0	TXD_1	RXD_0	RXD_1	CLK_0	CLK_1	TXD2	RXD2	$\overline{CTS2}$	$\overline{RTS2}$	SDA2	SCL2	CLK2
P0_0	72																		
P0_1	71							TXD_1											
P0_2	70									RXD_1									
P0_3	69											CLK_1							
P0_4	68																		
P0_5	67																		
P0_6	66																		
P0_7	65																		
P1_0	56																		
P1_1	55																		
P1_2	54																		
P1_3	53																		
P1_4	52						TXD_0												
P1_5	51		$\overline{INT1}$						RXD_0										
P1_6	50										CLK_0								
P1_7	49		$\overline{INT1}$																
P2_0	30		$\overline{INT1}$																
P2_1	29																		
P2_2	28																		
P2_3	27																		
P2_4	26																		
P2_5	25																		
P2_6	24																		
P2_7	23																		
P3_0	4																		
P3_1	36																		
P3_2	3		$\overline{INT1}$	$\overline{INT2}$															
P3_3	22				$\overline{INT3}$										$\overline{CTS2}$	$\overline{RTS2}$			
P3_4	21												TXD2	RXD2			SDA2	SCL2	
P3_5	20																		CLK2
P3_6	35																		
P3_7	19												TXD2	RXD2			SDA2	SCL2	
P4_2	5																		
P4_3	7																		
P4_4	8																		
P4_5	48	$\overline{INT0}$												RXD2				SCL2	
P4_6	12																		
P4_7	10																		
P5_0	18																		
P5_1	17																		
P5_2	16																		
P5_3	15																		
P5_4	14																		
P5_5	2																		
P5_6	1																		
P5_7	80																		
P6_0	77																		
P6_1	76																		
P6_2	75											CLK_1							
P6_3	74							TXD_1											
P6_4	73									RXD_1									
P6_5	47					$\overline{INT4}$						CLK_1							CLK2
P6_6	46			$\overline{INT2}$									TXD2				SDA2		
P6_7	45				$\overline{INT3}$														
P7_0	64																		
P7_1	63																		
P7_2	62																		
P7_3	61																		
P7_4	60																		
P7_5	59																		
P7_6	58																		
P7_7	57																		

Table 1.5 Pin Name Information by Pin Number (INT, URAT0, and UART2) (2)

Port	Pin No.	INT					UART0						UART2						
		$\overline{INT0}$	$\overline{INT1}$	$\overline{INT2}$	$\overline{INT3}$	$\overline{INT4}$	TXD_0	TXD_1	RXD_0	RXD_1	CLK_0	CLK_1	TXD2	RXD2	$\overline{CTS2}$	$\overline{RTS2}$	SDA2	SCL2	CLK2
P8_0	44																		
P8_1	43																		
P8_2	42																		
P8_3	41																		
P8_4	40																		
P8_5	39																		
P8_6	38																		
P8_7	37																		
P9_0	34																		
P9_1	33																		
P9_2	32																		
P9_3	31																		
P9_4	79																		
P9_5	78																		

Table 1.6 Pin Name Information by Pin Number (SSU/I²C, Timer RJ, and Timer RB2) (1)

Port	Pin No.	SSU/I²C						Timer RJ		Timer RB2
		SCL_0	SDA_0	SSI_0	$\overline{SCS\_0}$	SSCK_0	SSO_0	TRJO_0	TRJIO_0	TRBO_0
P0_0	72									
P0_1	71									
P0_2	70									
P0_3	69									
P0_4	68									
P0_5	67									
P0_6	66									
P0_7	65									
P1_0	56									
P1_1	55									
P1_2	54									
P1_3	53									TRBO_0
P1_4	52									
P1_5	51								TRJIO_0	
P1_6	50									
P1_7	49									
P2_0	30									
P2_1	29									
P2_2	28									
P2_3	27									
P2_4	26									
P2_5	25									
P2_6	24									
P2_7	23									
P3_0	4							TRJO_0		
P3_1	36									
P3_2	3								TRJIO_0	
P3_3	22				$\overline{SCS\_0}$					
P3_4	21			SSI_0						
P3_5	20	SCL_0				SSCK_0				
P3_6	35									
P3_7	19		SDA_0				SSO_0			
P4_2	5									
P4_3	7									
P4_4	8									
P4_5	48									
P4_6	12									
P4_7	10									
P5_0	18									
P5_1	17									
P5_2	16									
P5_3	15									
P5_4	14									
P5_5	2								TRJIO_0	
P5_6	1									
P5_7	80									
P6_0	77									
P6_1	76									
P6_2	75									
P6_3	74									
P6_4	73									
P6_5	47									
P6_6	46									
P6_7	45									
P7_0	64									
P7_1	63									
P7_2	62									
P7_3	61									
P7_4	60									
P7_5	59									
P7_6	58									
P7_7	57									

Table 1.7 Pin Name Information by Pin Number (SSU/I²C, Timer RJ, and Timer RB2) (2)

Port	Pin No.	SSU/I²C						Timer RJ		Timer RB2
		SCL_0	SDA_0	SSI_0	$\overline{SCS\_0}$	SSCK_0	SSO_0	TRJO_0	TRJIO_0	TRBO_0
P8_0	44									
P8_1	43									
P8_2	42									
P8_3	41									
P8_4	40									
P8_5	39									
P8_6	38									
P8_7	37									
P9_0	34									
P9_1	33									
P9_2	32									
P9_3	31									
P9_4	79									
P9_5	78									

Table 1.8 Pin Name Information by Pin Number (Timer RC, Timer RE2, and Others) (1)

Port	Pin No.	Timer RC						Timer RE2	Others		
		TRCCLK_0	TRCIOA_0	TRCIOB_0	TRCIOC_0	TRCIOD_0	TRCTRG_0	TMRE2O			
P0_0	72		TRCIOA_0				TRCTRG_0		AN7		
P0_1	71		TRCIOA_0				TRCTRG_0		AN6		
P0_2	70		TRCIOA_0				TRCTRG_0		AN5		
P0_3	69			TRCIOB_0					AN4		
P0_4	68			TRCIOB_0				TMRE2O	AN3		
P0_5	67			TRCIOB_0					AN2		
P0_6	66					TRCIOD_0			AN1		
P0_7	65				TRCIOC_0				AN0		
P1_0	56					TRCIOD_0			AN8	$\overline{KI0}$	
P1_1	55		TRCIOA_0				TRCTRG_0		AN9	$\overline{KI1}$	
P1_2	54			TRCIOB_0					AN10	$\overline{KI2}$	
P1_3	53				TRCIOC_0				AN11	$\overline{KI3}$	
P1_4	52	TRCCLK_0									
P1_5	51										
P1_6	50								IVREF1		CH00
P1_7	49								IVCMP1		CH01
P2_0	30			TRCIOB_0							CH16
P2_1	29				TRCIOC_0						CH17
P2_2	28					TRCIOD_0					CH18
P2_3	27										CH19
P2_4	26										CH20
P2_5	25										CH21
P2_6	24										CH22
P2_7	23										CH23
P3_0	4										CH24
P3_1	36										CH10
P3_2	3										CH25
P3_3	22	TRCCLK_0							IVCMP3		
P3_4	21				TRCIOC_0				IVREF3		
P3_5	20					TRCIOD_0					
P3_6	35										CH11
P3_7	19										
P4_2	5								VREF		
P4_3	7								XCIN		
P4_4	8								XCOUT		
P4_5	48								$\overline{ADTRG}$		CH02
P4_6	12								XIN		
P4_7	10								XOUT		
P5_0	18	TRCCLK_0									
P5_1	17		TRCIOA_0				TRCTRG_0				
P5_2	16			TRCIOB_0							
P5_3	15				TRCIOC_0						
P5_4	14					TRCIOD_0					
P5_5	2										CH26
P5_6	1										CH27
P5_7	80										CH28
P6_0	77							TMRE2O			CH31
P6_1	76										CH32
P6_2	75										CH33
P6_3	74										CH34
P6_4	73										CH35
P6_5	47			TRCIOB_0							CH03
P6_6	46				TRCIOC_0						CH04
P6_7	45					TRCIOD_0					CH05
P7_0	64								AN12		
P7_1	63								AN13		
P7_2	62								AN14		
P7_3	61								AN15		
P7_4	60								AN16		
P7_5	59								AN17		
P7_6	58								AN18		
P7_7	57								AN19		

Table 1.9 Pin Name Information by Pin Number (Timer RC, Timer RE2, and Others) (2)

Port	Pin No.	Timer RC						Timer RE2	Others		
		TRCCLK_0	TRCIOA_0	TRCIOB_0	TRCIOC_0	TRCIOD_0	TRCTRG_0	TMRE2O			
P8_0	44										CH06
P8_1	43										CH07
P8_2	42										CHxA0
P8_3	41										CHxA1
P8_4	40										CHxB
P8_5	39										CHxC
P8_6	38										CH08
P8_7	37										CH09
P9_0	34										CH12
P9_1	33										CH13
P9_2	32										CH14
P9_3	31										CH15
P9_4	79										CH29
P9_5	78										CH30

1.5 Pin Functions

Tables 1.10 and 1.11 list Pin Functions.

Table 1.10 Pin Functions (1)

Item	Pin Name	I/O	Description
Power supply input	VCC, VSS	—	Apply 1.8 V through 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	—	Power supply input for the A/D converter. Connect a capacitor between pins AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Applying a low level to this pin resets the MCU.
MODE	MODE	I	Connect this pin to the VCC pin via a resistor.
XIN clock input	XIN	I	I/O for the XIN clock generation circuit. Connect a ceramic resonator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	I/O	
XCIN clock input	XCIN	I	I/O for the XCIN clock generation circuit. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCOUT pin and leave the XCIN pin open.
XCIN clock output	XCOUT	I/O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT4}}$	I	$\overline{\text{INT}}$ interrupt input.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input.
Timer RJ_0	TRJIO_0	I/O	Input/output for timer RJ.
	TRJO_0	O	Output for timer RJ.
Timer RB2_0	TRBO_0	O	Output for timer RB2.
Timer RC_0	TRCCLK_0	I	External clock input.
	TRCTRG_0	I	External trigger input.
	TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0	I/O	Input/output for timer RC.
Timer RE2	TMRE2O	O	Divided clock output.
Serial interface (UART0)	CLK_0, CLK_1	I/O	Transfer clock input/output.
	RXD_0, RXD_1	I	Serial data input.
	TXD_0, TXD_1	O	Serial data output.
Serial interface (UART2)	$\overline{\text{CTS2}}$	I	Input for transmission control.
	$\overline{\text{RTS2}}$	O	Output for reception control.
	SCL2	I/O	I^2C mode clock input/output.
	SDA2	I/O	I^2C mode data input/output.
	RXD2	I	Serial data input.
	TXD2	O	Serial data output.
	CLK2	I/O	Transfer clock input/output.
Synchronous serial communication unit (SSU_0)	SSI_0	I/O	Data input/output.
	$\overline{\text{SCS\_0}}$	I/O	Chip-select input/output.
	SSCK_0	I/O	Clock input/output.
	SSO_0	I/O	Data input/output.
I^2C bus (I^2C_0)	SCL_0	I/O	Clock input/output.
	SDA_0	I/O	Data input/output.
Reference voltage input	VREF	I	Reference voltage input for the A/D converter.

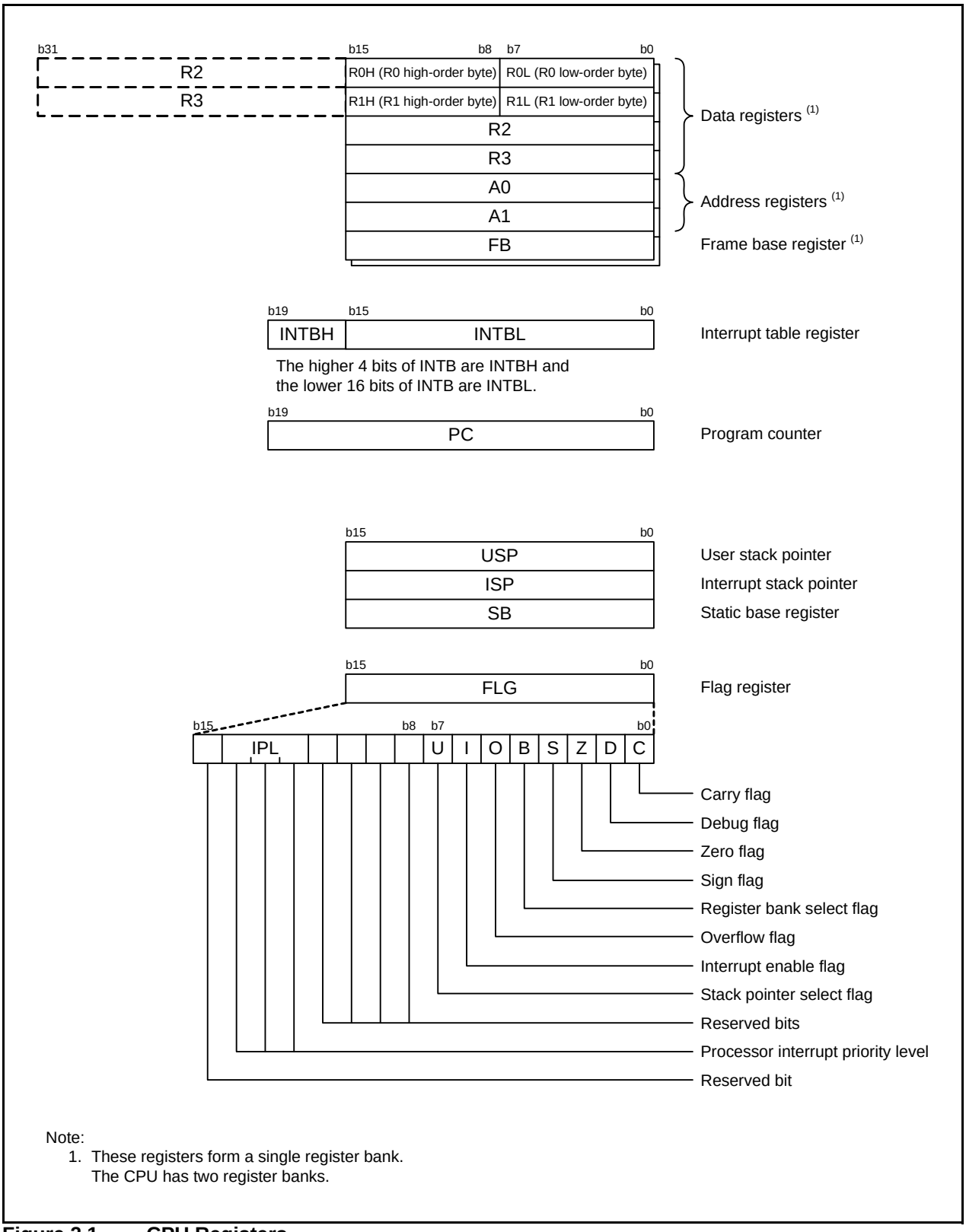
Note:
1. Contact the oscillator manufacturer for oscillation characteristics.

Table 1.11 Pin Functions (2)

Item	Pin Name	I/O	Description
A/D converter	AN0 to AN19	I	Analog input for the A/D converter.
	$\overline{\text{ADTRG}}$	I	External trigger input for the A/D converter.
Comparator B	IVCMP1, IVCMP3	I	Analog voltage input for comparator B.
	IVREF1, IVREF3	I	Reference voltage input for comparator B.
Touch sensor control unit	CHxA0, CHxA1, CHxB, CHxC	I/O	Control pins for electrostatic capacitive touch detection.
	CH00 to CH35	I	Electrostatic capacitive touch detection pins.
I/O ports	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_3 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_5	I/O	8-bit CMOS input/output ports. Each port has an I/O select direction register, enabling switching input and output for each pin. For input ports, the presence or absence of a pull-up resistor can be selected by a program. All ports can be used as LED drive (high drive) ports.
Input port	P4_2	I	Input-only port.

2. Central Processing Unit (CPU)

Figure 2.1 shows the 13 CPU Registers. The registers R0, R1, R2, R3, A0, A1, and FB form a single register bank. The CPU has two register banks.



Note:
1. These registers form a single register bank.
The CPU has two register banks.

Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 through R3. R0 can be split into high-order (R0H) and low-order (R0L) registers to be used separately as 8-bit data registers. The same applies to R1H and R1L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). Similarly, R3 and R1 can be used as a 32-bit data register.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 functions in the same manner as A0. A1 can be combined with A0 and used as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register used for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of a relocatable interrupt vector table.

2.5 Program Counter (PC)

PC is a 20-bit register that indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of the FLG register is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register used for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register that indicates the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated in the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. It must only be set to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0. Otherwise it is set to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value. Otherwise it is set to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow. Otherwise it is set to 0.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts. Interrupts are disabled when the I flag is 0, and are enabled when the I flag is 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is 0. USP is selected when the U flag is 1. The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction for a software interrupt numbered from 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns eight processor interrupt priority levels from 0 to 7. If a requested interrupt has higher priority than IPL, the interrupt is enabled.

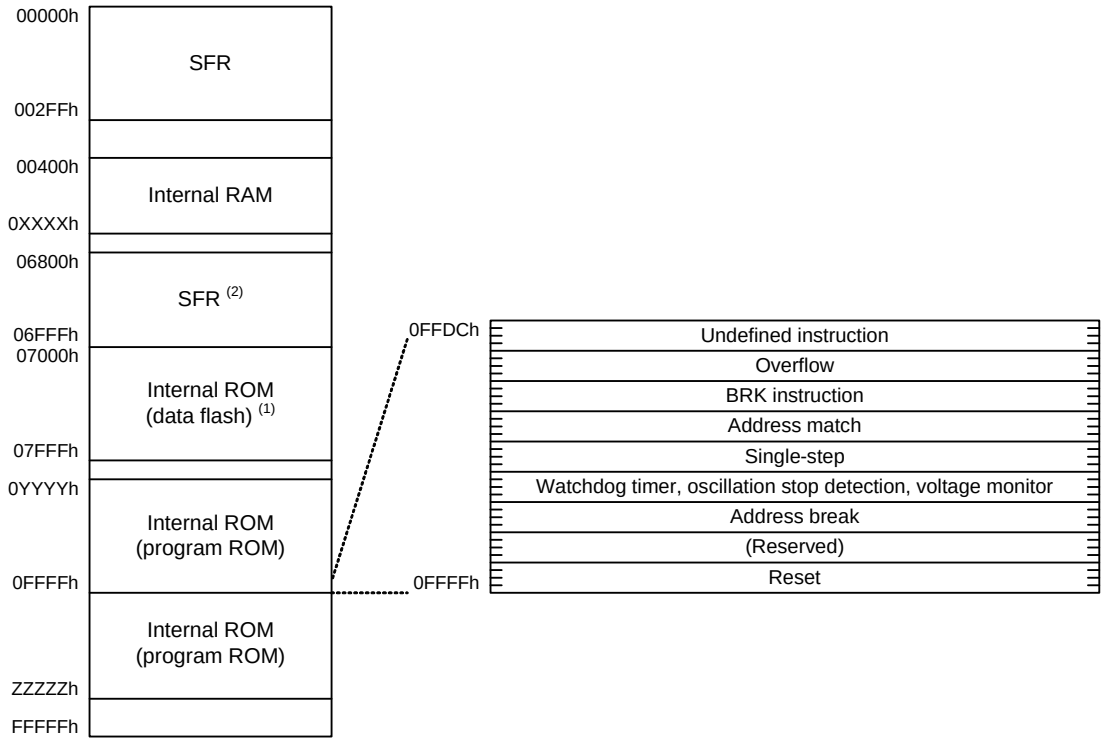
2.8.10 Reserved Bit

The write value must be 0. The read value is undefined.

3. Address Space

3.1 Memory Map

Figure 3.1 shows the Memory Map. The R8C/38T-A Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. Up to 32 Kbytes of the internal ROM (program ROM) is allocated at lower addresses, beginning with address 0FFFFh. The area in excess of 32 Kbytes is allocated at higher addresses, beginning with address 10000h. For example, a 64-Kbyte internal ROM is allocated at addresses 08000h to 17FFFh.
The fixed interrupt vector table is allocated at addresses 0FFDCh to 0FFFFh. The start address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated at addresses 07000h to 07FFFh.
The internal RAM is allocated at higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM is allocated at addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated at addresses 00000h to 02FFFh and addresses 06800h to 06FFFh. Peripheral function control registers are allocated here. All unallocated locations within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Addresses 06800h to 06FFFh are used for the ELC, DTC, and TSCU SFR areas.
3. The blank areas are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F21388SNFP, R5F21388SDFP	64 Kbytes	08000h	17FFFh	6 Kbytes	01BFFh
R5F21388SNFP, R5F21388SDFP	96 Kbytes	08000h	1FFFFh	8 Kbytes	023FFh
R5F21388SNFP, R5F21388SDFP	128 Kbytes	08000h	27FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

3.2 Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 3.1 to 3.16 list the SFR Information. Table 3.17 lists the ID code Area, Option Function Select Area.

Table 3.1 SFR Information (1) (1)

Address	Symbol	Register Name	After Reset	Remarks
00000h				
00001h				
00002h				
00003h				
00004h	PM0	Processor Mode Register 0	00h	
00005h	PM1	Processor Mode Register 1	10000000b	
00006h				
00007h	PRCR	Protect Register	00h	
00008h	CM0	System Clock Control Register 0	00101000b	
00009h	CM1	System Clock Control Register 1	00100000b	
0000Ah	OCD	Oscillation Stop Detection Register	00h	
0000Bh	CM3	System Clock Control Register 3	00h	
0000Ch	CM4	System Clock Control Register 4	00000001b	
0000Dh				
0000Eh				
0000Fh				
00010h	CPSRF	Clock Prescaler Reset Flag	00h	
00011h				
00012h	FRA0	High-Speed On-Chip Oscillator Control Register 0	00h	
00013h				
00014h	FRA2	High-Speed On-Chip Oscillator Control Register 2	00h	
00015h				
00016h				
00017h				
00018h				
00019h				
0001Ah				
0001Bh				
0001Ch				
0001Dh				
0001Eh				
0001Fh				
00020h	RISR	Reset Interrupt Select Register	10000000b or 00000000b	(Note 2)
00021h	WDTR	Watchdog Timer Reset Register	FFh	
00022h	WDTS	Watchdog Timer Start Register	FFh	
00023h	WDTC	Watchdog Timer Control Register	01111111b	
00024h	CSPR	Count Source Protection Mode Register	10000000b or 00000000b	(Note 2)
00025h				
00026h				
00027h				
00028h	RSTFR	Reset Source Determination Register	00XXXXXXb	
00029h				
0002Ah				
0002Bh				
0002Ch	SVDC	STBY VDC Power Control Register	00h	
0002Dh				
0002Eh				
0002Fh				
00030h	CMPA	Voltage Monitor Circuit Control Register	00h	
00031h	VCAC	Voltage Monitor Circuit Edge Select Register	00h	
00032h	OCVREFCR	On-Chip Reference Voltage Control Register	00h	
00033h				
00034h	VCA2	Voltage Detection Register 2	00000000b or 00100000b	(Note 3)
00035h				
00036h	VD1LS	Voltage Detection 1 Level Select Register	00000111b	
00037h				
00038h	VW0C	Voltage Monitor 0 Circuit Control Register	1100XX10b or 1100XX11b	(Note 3)
00039h	VW1C	Voltage Monitor 1 Circuit Control Register	10001010b	

X: Undefined

Notes:

1. The blank areas are reserved. No access is allowed.
2. Depends on the CSPROINI bit in the OFS register.
3. Depends on the LVDASI bit in the OFS register.

Table 3.2 SFR Information (2) (1)

Address	Symbol	Register Name	After Reset	Remarks
0003Ah	VW2C	Voltage Monitor 2 Circuit Control Register	10001010b	
0003Bh				
0003Ch				
0003Dh				
0003Eh				
0003Fh				
00040h				
00041h	FMRDYIC	Interrupt Control Register	00h	
00042h				
00043h				
00044h				
00045h				
00046h	INT4IC	Interrupt Control Register	00h	
00047h	TRCIC_0	Interrupt Control Register	00h	
00048h				
00049h				
0004Ah	TRE2IC	Interrupt Control Register	00h	
0004Bh	U2TIC	Interrupt Control Register	00h	
0004Ch	U2RIC	Interrupt Control Register	00h	
0004Dh	KUPIC	Interrupt Control Register	00h	
0004Eh	ADIC	Interrupt Control Register	00h	
0004Fh	SSUIC_0/IICIC_0	Interrupt Control Register	00h	
00050h				
00051h	U0TIC_0	Interrupt Control Register	00h	
00052h	U0RIC_0	Interrupt Control Register	00h	
00053h	U0TIC_1	Interrupt Control Register	00h	
00054h	U0RIC_1	Interrupt Control Register	00h	
00055h	INT2IC	Interrupt Control Register	00h	
00056h	TRJIC_0	Interrupt Control Register	00h	
00057h				
00058h	TRB2IC_0	Interrupt Control Register	00h	
00059h	INT1IC	Interrupt Control Register	00h	
0005Ah	INT3IC	Interrupt Control Register	00h	
0005Bh				
0005Ch				
0005Dh	INT0IC	Interrupt Control Register	00h	
0005Eh	U2BCNIC	Interrupt Control Register	00h	
0005Fh				
00060h				
00061h				
00062h				
00063h				
00064h				
00065h				
00066h				
00067h				
00068h				
00069h				
0006Ah				
0006Bh				
0006Ch				
0006Dh				
0006Eh				
0006Fh				
00070h				
00071h				
00072h	VCMP1IC	Interrupt Control Register	00h	
00073h	VCMP2IC	Interrupt Control Register	00h	
00074h				
00075h	TSCUIC	Interrupt Control Register	00h	
00076h				
00077h				
00078h				
00079h				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.3 SFR Information (3) (1)

Address	Symbol	Register Name	After Reset	Remarks
0007Ah				
0007Bh				
0007Ch				
0007Dh				
0007Eh				
0007Fh				
00080h	U0MR_0	UART0_0 Transmit/Receive Mode Register	00h	
00081h	U0BRG_0	UART0_0 Bit Rate Register	XXh	
00082h	U0TB_0	UART0_0 Transmit Buffer Register	XXh	
00083h			XXh	
00084h	U0C0_0	UART0_0 Transmit/Receive Control Register 0	00001000b	
00085h	U0C1_0	UART0_0 Transmit/Receive Control Register 1	00000010b	
00086h	U0RB_0	UART0_0 Receive Buffer Register	XXXXh	
00087h				
00088h	U0IR_0	UART0_0 Interrupt Flag and Enable Register	00h	
00089h				
0008Ah				
0008Bh				
0008Ch	LINCR2_0	LIN_0 Special Function Register	00h	
0008Dh				
0008Eh	LINCT_0	LIN_0 Control Register	00h	
0008Fh	LINST_0	LIN_0 Status Register	00h	
00090h	U0MR_1	UART0_1 Transmit/Receive Mode Register	00h	
00091h	U0BRG_1	UART0_1 Bit Rate Register	XXh	
00092h	U0TB_1	UART0_1 Transmit Buffer Register	XXh	
00093h			XXh	
00094h	U0C0_1	UART0_1 Transmit/Receive Control Register 0	00001000b	
00095h	U0C1_1	UART0_1 Transmit/Receive Control Register 1	00000010b	
00096h	U0RB_1	UART0_1 Receive Buffer Register	XXXXh	
00097h				
00098h	U0IR_1	UART0_1 Interrupt Flag and Enable Register	00h	
00099h				
0009Ah				
0009Bh				
0009Ch				
0009Dh				
0009Eh				
0009Fh				
000A0h				
000A1h				
000A2h				
000A3h				
000A4h				
000A5h				
000A8h				
000A9h				
000AAh				
000ABh				
000ACh				
000ADh				
000AEh				
000AFh				
000B0h				
000B1h				
000B4h				
000B5h				
000B8h				
000B9h				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.4 SFR Information (4) (1)

Address	Symbol	Register Name	After Reset	Remarks
000BAh				
000BBh				
000BCh				
000BDh				
000BEh				
000BFh				
000C0h	U2MR	UART2 Transmit/Receive Mode Register	00h	
000C1h	U2BRG	UART2 Bit Rate Register	00h	
000C2h	U2TB	UART2 Transmit Buffer Register	00h	
000C3h			00h	
000C4h	U2C0	UART2 Transmit/Receive Control Register 0	00001000b	
000C5h	U2C1	UART2 Transmit/Receive Control Register 1	00000010b	
000C6h	U2RB	UART2 Receive Buffer Register	0000h	
000C7h				
000C8h	U2RXDF	UART2 Digital Filter Function Select Register	00h	
000C9h				
000CAh				
000CBh				
000CCh				
000CDh				
000CEh				
000CFh				
000D0h	U2SMR5	UART2 Special Mode Register 5	00h	
000D1h				
000D2h				
000D3h				
000D4h	U2SMR4	UART2 Special Mode Register 4	00h	
000D5h	U2SMR3	UART2 Special Mode Register 3	00h	
000D6h	U2SMR2	UART2 Special Mode Register 2	00h	
000D7h	U2SMR	UART2 Special Mode Register	00h	
000D8h				
000D9h				
000DAh				
000DBh				
000DCh				
000DDh				
000DEh				
000DFh				
000E0h	IICCR_0	I^2C_0 Control Register	00001110b	
000E1h	SSBR_0	SS_0 Bit Counter Register	11111000b	
000E2h	SITDR_0	SI_0 Transmit Data Register	FFh	
000E3h			FFh	
000E4h	SIRDR_0	SI_0 Receive Data Register	FFh	
000E5h			FFh	
000E6h	SICR1_0	SI_0 Control Register 1	00h	
000E7h	SICR2_0	SI_0 Control Register 2	01111101b	
000E8h	SIMR1_0	SI_0 Mode Register 1	00010000b	
000E9h	SIER_0	SI_0 Interrupt Enable Register	00h	
000EAh	SISR_0	SI_0 Status Register	00h	
000EBh	SIMR2_0	SI_0 Mode Register 2	00h	
000ECh				
000EDh				
000EEh				
000EFh				
000F0h				
000F1h				
000F2h				
000F3h				
000F4h				
000F5h				
000F6h				
000F7h				
000F8h				
000F9h				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.5 SFR Information (5) (1)

Address	Symbol	Register Name	After Reset	Remarks
000FAh				
000FBh				
000FCh				
000FDh				
000FEh				
000FFh				
00100h				
00101h				
00102h				
00103h				
00104h				
00105h				
00106h				
00107h				
00108h				
00109h				
0010Ah				
0010Bh				
0010Ch				
0010Dh				
0010Eh				
0010Fh				
00110h	TRJ_0	Timer RJ_0 Counter Register	FFFFh	
00111h				
00112h	TRJCR_0	Timer RJ_0 Control Register	00h	
00113h	TRJIOC_0	Timer RJ_0 I/O Control Register	00h	
00114h	TRJMR_0	Timer RJ_0 Mode Register	00h	
00115h	TRJISR_0	Timer RJ_0 Event Pin Select Register	00h	
00116h				
00117h				
00118h				
00119h				
0011Ah				
0011Bh				
0011Ch				
0011Dh				
0011Eh				
0011Fh				
00120h				
00121h				
00122h				
00123h				
00124h				
00125h				
00126h				
00127h				
00128h				
00129h				
0012Ah				
0012Bh				
0012Ch				
0012Dh				
0012Eh				
0012Fh				
00130h	TRBCR_0	Timer RB2_0 Control Register	00h	
00131h	TRBOCR_0	Timer RB2_0 One-Shot Control Register	00h	
00132h	TRBIOC_0	Timer RB2_0 I/O Control Register	00h	
00133h	TRBMR_0	Timer RB2_0 Mode Register	00h	
00134h	TRBPRE_0	Timer RB2_0 Prescaler Register	FFh	
00135h	TRBPR_0	Timer RB2_0 Primary Register	FFh	
00136h	TRBSC_0	Timer RB2_0 Secondary Register	FFh	
00137h	TRBIR_0	Timer RB2_0 Interrupt Request Register	00h	
00138h	TRCCNT_0	Timer RC_0 Counter	0000h	
00139h				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.6 SFR Information (6) (1)

Address	Symbol	Register Name	After Reset	Remarks
0013Ah	TRCGRA_0	Timer RC_0 General Register A	FFFFh	
0013Bh				
0013Ch	TRCGRB_0	Timer RC_0 General Register B	FFFFh	
0013Dh				
0013Eh	TRCGRC_0	Timer RC_0 General Register C	FFFFh	
0013Fh				
00140h	TRCGRD_0	Timer RC_0 General Register D	FFFFh	
00141h				
00142h	TRCMR_0	Timer RC_0 Mode Register	01001000b	
00143h	TRCCR1_0	Timer RC_0 Control Register 1	00h	
00144h	TRCIER_0	Timer RC_0 Interrupt Enable Register	01110000b	
00145h	TRCSR_0	Timer RC_0 Status Register	01110000b	
00146h	TRCIOR0_0	Timer RC_0 I/O Control Register 0	10001000b	
00147h	TRCIOR1_0	Timer RC_0 I/O Control Register 1	10001000b	
00148h	TRCCR2_0	Timer RC_0 Control Register 2	00011000b	
00149h	TRCDF_0	Timer RC_0 Digital Filter Function Select Register	00h	
0014Ah	TRCOER_0	Timer RC_0 Output Enable Register	01111111b	
0014Bh	TRCADCR_0	Timer RC_0 A/D Conversion Trigger Control Register	11110000b	
0014Ch	TRCOPR_0	Timer RC_0 Output Waveform Manipulation Register	00h	
0014Dh	TRCELCCR_0	Timer RC_0 ELC Cooperation Control Register	00h	
0014Eh				
0014Fh				
00150h				
00151h				
00152h				
00153h				
00154h				
00155h				
00156h				
00157h				
00158h				
00159h				
0015Ah				
0015Bh				
0015Ch				
0015Dh				
0015Eh				
0015Fh				
00160h				
00161h				
00162h				
00163h				
00164h				
00165h				
00166h				
00167h				
00168h				
00169h				
0016Ah				
0016Bh				
0016Ch				
0016Dh				
0016Eh				
0016Fh				
00170h	TRESEC	Timer RE2 Counter Data Register Timer RE2 Second Data Register	00h	
00171h	TREMIN	Timer RE2 Compare Data Register Timer RE2 Minute Data Register	00h	
00172h	TREHR	Timer RE2 Hour Data Register	00h	
00173h	TREWK	Timer RE2 Day-of-the-Week Data Register	00h	
00174h	TREDY	Timer RE2 Day Data Register	00000001b	
00175h	TREMON	Timer RE2 Month Data Register	00000001b	
00176h	TREYR	Timer RE2 Year Data Register	00h	
00177h	TRECR	Timer RE2 Control Register	00000100b	
00178h	TRECSR	Timer RE2 Count Source Select Register	00001000b	
00179h	TREADJ	Timer RE2 Clock Error Correction Register	00h	

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.7 SFR Information (7) (1)

Address	Symbol	Register Name	After Reset	Remarks
0017Ah	TREIFR	Timer RE2 Interrupt Flag Register	00h	
0017Bh	TREIER	Timer RE2 Interrupt Enable Register	00h	
0017Ch	TREAMN	Timer RE2 Alarm Minute Register	00h	
0017Dh	TREAHR	Timer RE2 Alarm Hour Register	00h	
0017Eh	TREAWK	Timer RE2 Alarm Day-of-the-Week Register	00h	
0017Fh	TREPRC	Timer RE2 Protect Register	00h	
00180h to 001FFh				
00200h	AD0	A/D Register 0	00h	
00201h			00h	
00202h	AD1	A/D Register 1	00h	
00203h			00h	
00204h	AD2	A/D Register 2	00h	
00205h			00h	
00206h	AD3	A/D Register 3	00h	
00207h			00h	
00208h	AD4	A/D Register 4	00h	
00209h			00h	
0020Ah	AD5	A/D Register 5	00h	
0020Bh			00h	
0020Ch	AD6	A/D Register 6	00h	
0020Dh			00h	
0020Eh	AD7	A/D Register 7	00h	
0020Fh			00h	
00210h				
00211h				
00212h				
00213h				
00214h	ADMOD	A/D Mode Register	00h	
00215h	ADINSEL	A/D Input Select Register	11000000b	
00216h	ADCON0	A/D Control Register 0	00h	
00217h	ADCON1	A/D Control Register 1	00h	
00218h				
00219h				
0021Ah				
0021Bh				
0021Ch				
0021Dh				
0021Eh				
0021Fh				
00220h				
00221h				
00222h				
00223h				
00224h				
00225h				
00226h				
00227h				
00228h	INTCMP	Comparator B Control Register 0	00h	
00229h				
0022Ah				
0022Bh				
0022Ch				
0022Dh				
0022Eh				
0022Fh				
00230h	INTEN	External Input Enable Register 0	00h	
00231h	INTEN1	External Input Enable Register 1	00h	
00232h	INTF	INT Input Filter Select Register 0	00h	
00233h	INTF1	INT Input Filter Select Register 1	00h	
00234h	INTPOL	INT Input Polarity Switch Register	00h	
00235h				
00236h	KIEN	Key Input Interrupt Enable Register	00h	
00237h				
00238h	MSTCR0	Module Standby Control Register 0	00h	
00239h	MSTCR1	Module Standby Control Register 1	00h	

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.8 SFR Information (8) (1)

Address	Symbol	Register Name	After Reset	Remarks
0023Ah	MSTCR2	Module Standby Control Register 2	00h	
0023Bh	MSTCR3	Module Standby Control Register 3	00h	
0023Ch	MSTCR4	Module Standby Control Register 4	00h	
0023Dh				
0023Eh				
0023Fh				
00240h				
00241h				
00242h				
00243h				
00244h				
00245h				
00246h				
00247h				
00248h				
00249h				
0024Ah				
0024Bh				
0024Ch				
0024Dh				
0024Eh				
0024Fh				
00250h				
00251h				
00252h	FST	Flash Memory Status Register	10000X00b	
00253h				
00254h	FMR0	Flash Memory Control Register 0	00h	
00255h	FMR1	Flash Memory Control Register 1	00h	
00256h	FMR2	Flash Memory Control Register 2	00h	
00257h				
00258h				
00259h				
0025Ah				
0025Bh				
0025Ch				
0025Dh				
0025Eh				
0025Fh				
00260h	AIADR0L	Address Match Interrupt Address 0L Register	XXXXh	
00261h				
00262h	AIADR0H	Address Match Interrupt Address 0H Register	0000XXXXb	
00263h	AIEN0	Address Match Interrupt Enable 0 Register	00h	
00264h	AIADR1L	Address Match Interrupt Address 1L Register	XXXXh	
00265h				
00266h	AIADR1H	Address Match Interrupt Address 1H Register	0000XXXXb	
00267h	AIEN1	Address Match Interrupt Enable 1 Register	00h	
00268h				
00269h				
0026Ah				
0026Bh				
0026Ch				
0026Dh				
0026Eh				
0026Fh				
00270h				
00271h				
00272h				
00273h				
00274h				
00275h				
00276h				
00277h				
00278h				
00279h				
0027Ah				
0027Bh				
0027Ch				
0027Dh				
0027Eh				
0027Fh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.9 SFR Information (9) (1)

Address	Symbol	Register Name	After Reset	Remarks
00280h	DTCTL	DTC Activation Control Register	00h	
00281h				
00282h				
00283h				
00284h				
00285h				
00286h				
00287h				
00288h	DTCEN0	DTC Activation Enable Register 0	00h	
00289h	DTCEN1	DTC Activation Enable Register 1	00h	
0028Ah	DTCEN2	DTC Activation Enable Register 2	00h	
0028Bh	DTCEN3	DTC Activation Enable Register 3	00h	
0028Ch				
0028Dh	DTCEN5	DTC Activation Enable Register 5	00h	
0028Eh	DTCEN6	DTC Activation Enable Register 6	00h	
0028Fh				
00290h	CRCSAR	SFR Snoop Address Register	0000h	
00291h				
00292h	CRCMR	CRC Control Register	00h	
00293h				
00294h	CRCD	CRC Data Register	0000h	
00295h				
00296h	CRCIN	CRC Input Register	00h	
00297h				
00298h				
00299h				
0029Ah				
0029Bh				
0029Ch				
0029Dh				
0029Eh				
0029Fh				
002A0h	TRJ_0SR	Timer RJ_0 Pin Select Register	08h	
002A1h				
002A2h				
002A3h				
002A4h				
002A5h	TRCCLKSR	Timer RCCLK Pin Select Register	00h	
002A6h	TRC_0SR0	Timer RC_0 Pin Select Register 0	00h	
002A7h	TRC_0SR1	Timer RC_0 Pin Select Register 1	00h	
002A8h				
002A9h				
002AAh				
002ABh				
002ACh				
002ADh	TIMSR	Timer Pin Select Register	00h	
002AEh	U_0SR	UART0_0 Pin Select Register	00h	
002AFh	U_1SR	UART0_1 Pin Select Register	00h	
002B0h				
002B1h				
002B2h	U2SR0	UART2 Pin Select Register 0	00h	
002B3h	U2SR1	UART2 Pin Select Register 1	00h	
002B4h				
002B5h				
002B6h	INTSR0	INT Interrupt Input Pin Select Register 0	00h	
002B7h				
002B8h				
002B9h	PINSR	I/O Function Pin Select Register	00h	
002BAh				
002BBh				
002BCh				
002BDh				
002BEh	PMCSEL	Pin Assignment Select Register	00h	
002BFh				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.10 SFR Information (10) (1)

Address	Symbol	Register Name	After Reset	Remarks
002C0h	PUR0	Pull-Up Control Register 0	00h	
002C1h	PUR1	Pull-Up Control Register 1	00h	
002C2h	PUR2	Pull-Up Control Register 2	00h	
002C3h				
002C4h				
002C5h				
002C6h				
002C7h				
002C8h	P1DRR	Port P1 Drive Capacity Control Register	00h	
002C9h	P2DRR	Port P2 Drive Capacity Control Register	00h	
002CAh				
002CBh				
002CCh	DRR0	Drive Capacity Control Register 0	00h	
002CDh	DRR1	Drive Capacity Control Register 1	00h	
002CEh	DRR2	Drive Capacity Control Register 2	00h	
002CFh				
002D0h	VLT0	Input Threshold Control Register 0	00h	
002D1h	VLT1	Input Threshold Control Register 1	00h	
002D2h	VLT2	Input Threshold Control Register 2	00h	
002D3h				
002D4h				
002D5h				
002D6h				
002D7h				
002D8h				
002D9h				
002DAh				
002DBh				
002DCh				
002DDh				
002DEh				
002DFh				
002E0h	PORT0	Port P0 Register	XXh	
002E1h	PORT1	Port P1 Register	XXh	
002E2h	PD0	Port P0 Direction Register	00h	
002E3h	PD1	Port P1 Direction Register	00h	
002E4h	PORT2	Port P2 Register	XXh	
002E5h	PORT3	Port P3 Register	XXh	
002E6h	PD2	Port P2 Direction Register	00h	
002E7h	PD3	Port P3 Direction Register	00h	
002E8h	PORT4	Port P4 Register	XXh	
002E9h	PORT5	Port P5 Register	XXh	
002EAh	PD4	Port P4 Direction Register	00h	
002EBh	PD5	Port P5 Direction Register	00h	
002ECh	PORT6	Port P6 Register	XXh	
002EDh	PORT7	Port P7 Register	XXh	
002EEh	PD6	Port P6 Direction Register	00h	
002EFh	PD7	Port P7 Direction Register	00h	
002F0h	PORT8	Port P8 Register	XXh	
002F1h	PORT9	Port P9 Register	XXh	
002F2h	PD8	Port P8 Direction Register	00h	
002F3h	PD9	Port P9 Direction Register	00h	
002F4h				
002F5h				
002F6h				
002F7h				
002F8h				
002F9h				
002FAh				
002FBh				
002FCh				
002FDh				
002FEh				
002FFh				
00300h to 003FFh				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.11 SFR Information (11) (1)

Address	Symbol	Register Name	After Reset	Remarks
00400h to 053FFh	On-chip RAM	On-chip RAM		
05400h to 069FFh				
06A00h	ELSELR0	Event Output Destination Select Register 0	00h	
06A01h	ELSELR1	Event Output Destination Select Register 1	00h	
06A02h	ELSELR2	Event Output Destination Select Register 2	00h	
06A03h	ELSELR3	Event Output Destination Select Register 3	00h	
06A04h	ELSELR4	Event Output Destination Select Register 4	00h	
06A05h				
06A06h				
06A07h				
06A08h	ELSELR8	Event Output Destination Select Register 8	00h	
06A09h	ELSELR9	Event Output Destination Select Register 9	00h	
06A0Ah				
06A0Bh	ELSELR11	Event Output Destination Select Register 11	00h	
06A0Ch	ELSELR12	Event Output Destination Select Register 12	00h	
06A0Dh	ELSELR13	Event Output Destination Select Register 13	00h	
06A0Eh	ELSELR14	Event Output Destination Select Register 14	00h	
06A0Fh	ELSELR15	Event Output Destination Select Register 15	00h	
06A10h	ELSELR16	Event Output Destination Select Register 16	00h	
06A11h				
06A12h				
06A13h				
06A14h				
06A15h				
06A16h				
06A17h				
06A18h				
06A19h				
06A1Ah				
06A1Bh				
06A1Ch				
06A1Dh				
06A1Eh				
06A1Fh				
06A20h				
06A21h				
06A22h				
06A23h				
06A24h				
06A25h				
06A26h				
06A27h				
06A28h				
06A29h				
06A2Ah				
06A2Bh				
06A2Ch				
06A2Dh				
06A2Eh				
06A2Fh				
06A30h				
06A31h to 06AFFh				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.12 SFR Information (12) (1)

Address	Symbol	Register Name	After Reset	Remarks
06B00h	TSCUCR0	TSCU Control Register 0	0000h	
06B01h				
06B02h	TSCUCR1	TSCU Control Register 1	0000000000010000b	
06B03h				
06B04h	TSCUMR	TSCU Mode Register	0000000010000000b	
06B05h				
06B06h	TSCUTCR0A	TSCU Timing Control Register 0A	0000000001111111b	
06B07h				
06B08h	TSCUTCR0B	TSCU Timing Control Register 0B	0000000001111111b	
06B09h				
06B0Ah	TSCUTCR1	TSCU Timing Control Register 1	0000000000000001b	
06B0Bh				
06B0Ch	TSCUTCR2	TSCU Timing Control Register 2	0000h	
06B0Dh				
06B0Eh	TSCUTCR3	TSCU Timing Control Register 3	0000h	
06B0Fh				
06B10h	TSCUCHC	TSCU Channel Control Register	0011111100000000b	
06B11h				
06B12h	TSCUFR	TSCU Flag Register	0000h	
06B13h				
06B14h	TSCUSTC	TSCU Status Counter Register	0000h	
06B15h				
06B16h	TSCUSCS	TSCU Secondary Counter Set Register	0000000000100000b	
06B17h				
06B18h	TSCUSCC	TSCU Secondary Counter	0000000000100000b	
06B19h				
06B1Ah	TSCUDBR	TSCU Data Buffer Register	0000h	
06B1Bh				
06B1Ch	TSCUPRC	TSCU Primary Counter	0000h	
06B1Dh				
06B1Eh	TSCURVR0	TSCU Random Value Store Register 0	0000h	
06B1Fh				
06B20h	TSCURVR1	TSCU Random Value Store Register 1	0000h	
06B21h				
06B22h	TSCURVR2	TSCU Random Value Store Register 2	0000h	
06B23h				
06B24h	TSCURVR3	TSCU Random Value Store Register 3	0000h	
06B25h				
06B26h	TSIE0	TSCU Input Enable Register 0	0000h	
06B27h				
06B28h	TSIE1	TSCU Input Enable Register 1	0000h	
06B29h				
06B2Ah	TSIE2	TSCU Input Enable Register 2	0000h	
06B2Bh				
06B2Ch	TSCHSEL0	TSCUCHXA Select Register 0	0000h	
06B2Dh				
06B2Eh	TSCHSEL1	TSCUCHXA Select Register 1	0000h	
06B2Fh				
06B30h	TSCHSEL2	TSCUCHXA Select Register 2	0000h	
06B31h				
06B32h to 06BFFh				
06C00h		Area for storing DTC transfer vector 0	XXh	
06C01h		Area for storing DTC transfer vector 1	XXh	
06C02h		Area for storing DTC transfer vector 2	XXh	
06C03h		Area for storing DTC transfer vector 3	XXh	
06C04h		Area for storing DTC transfer vector 4	XXh	
06C05h				
06C06h				
06C07h				
06C08h		Area for storing DTC transfer vector 8	XXh	
06C09h		Area for storing DTC transfer vector 9	XXh	

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.13 SFR Information (13) (1)

Address	Symbol	Register Name	After Reset	Remarks
06C0Ah		Area for storing DTC transfer vector 10	XXh	
06C0Bh		Area for storing DTC transfer vector 11	XXh	
06C0Ch		Area for storing DTC transfer vector 12	XXh	
06C0Dh		Area for storing DTC transfer vector 13	XXh	
06C0Eh		Area for storing DTC transfer vector 14	XXh	
06C0Fh		Area for storing DTC transfer vector 15	XXh	
06C10h		Area for storing DTC transfer vector 16	XXh	
06C11h		Area for storing DTC transfer vector 17	XXh	
06C12h		Area for storing DTC transfer vector 18	XXh	
06C13h		Area for storing DTC transfer vector 19	XXh	
06C14h				
06C15h				
06C16h		Area for storing DTC transfer vector 22	XXh	
06C17h		Area for storing DTC transfer vector 23	XXh	
06C18h		Area for storing DTC transfer vector 24	XXh	
06C19h		Area for storing DTC transfer vector 25	XXh	
06C1Ah				
06C1Bh				
06C1Ch				
06C1Dh				
06C1Eh				
06C1Fh				
06C20h				
06C21h				
06C22h				
06C23h				
06C24h				
06C25h				
06C26h				
06C27h				
06C28h				
06C29h				
06C2Ah		Area for storing DTC transfer vector 42	XXh	
06C2Bh				
06C2Ch				
06C2Dh				
06C2Eh				
06C2Fh				
06C30h				
06C31h		Area for storing DTC transfer vector 49	XXh	
06C32h				
06C33h		Area for storing DTC transfer vector 51	XXh	
06C34h		Area for storing DTC transfer vector 52	XXh	
06C35h		Area for storing DTC transfer vector 53	XXh	
06C36h		Area for storing DTC transfer vector 54	XXh	
06C37h				
06C38h				
06C39h				
06C3Ah				
06C3Bh				
06C3Ch				
06C3Dh				
06C3Eh				
06C3Fh				
06C40h	DTCCR0	DTC Control Register 0	XXh	
06C41h	DTBLS0	DTC Block Size Register 0	XXh	
06C42h	DTCCT0	DTC Transfer Count Register 0	XXh	
06C43h	DTRLD0	DTC Transfer Count Reload Register 0	XXh	
06C44h	DTSAR0	DTC Source Address Register 0	XXXXh	
06C45h				
06C46h	DTDAR0	DTC Destination Address Register 0	XXXXh	
06C47h				
06C48h	DTCCR1	DTC Control Register 1	XXh	
06C49h	DTBLS1	DTC Block Size Register 1	XXh	

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.14 SFR Information (14) (1)

Address	Symbol	Register Name	After Reset	Remarks
06C4Ah	DTCCT1	DTC Transfer Count Register 1	XXh	
06C4Bh	DTRLD1	DTC Transfer Count Reload Register 1	XXh	
06C4Ch	DTSAR1	DTC Source Address Register 1	XXXXh	
06C4Dh				
06C4Eh	DTDAR1	DTC Destination Address Register 1	XXXXh	
06C4Fh				
06C50h	DTCCR2	DTC Control Register 2	XXh	
06C51h	DTBLS2	DTC Block Size Register 2	XXh	
06C52h	DTCCT2	DTC Transfer Count Register 2	XXh	
06C53h	DTRLD2	DTC Transfer Count Reload Register 2	XXh	
06C54h	DTSAR2	DTC Source Address Register 2	XXXXh	
06C55h				
06C56h	DTDAR2	DTC Destination Address Register 2	XXXXh	
06C57h				
06C58h	DTCCR3	DTC Control Register 3	XXh	
06C59h	DTBLS3	DTC Block Size Register 3	XXh	
06C5Ah	DTCCT3	DTC Transfer Count Register 3	XXh	
06C5Bh	DTRLD3	DTC Transfer Count Reload Register 3	XXh	
06C5Ch	DTSAR3	DTC Source Address Register 3	XXXXh	
06C5Dh				
06C5Eh	DTDAR3	DTC Destination Address Register 3	XXXXh	
06C5Fh				
06C60h	DTCCR4	DTC Control Register 4	XXh	
06C61h	DTBLS4	DTC Block Size Register 4	XXh	
06C62h	DTCCT4	DTC Transfer Count Register 4	XXh	
06C63h	DTRLD4	DTC Transfer Count Reload Register 4	XXh	
06C64h	DTSAR4	DTC Source Address Register 4	XXXXh	
06C65h				
06C66h	DTDAR4	DTC Destination Address Register 4	XXXXh	
06C67h				
06C68h	DTCCR5	DTC Control Register 5	XXh	
06C69h	DTBLS5	DTC Block Size Register 5	XXh	
06C6Ah	DTCCT5	DTC Transfer Count Register 5	XXh	
06C6Bh	DTRLD5	DTC Transfer Count Reload Register 5	XXh	
06C6Ch	DTSAR5	DTC Source Address Register 5	XXXXh	
06C6Dh				
06C6Eh	DTDAR5	DTC Destination Address Register 5	XXXXh	
06C6Fh				
06C70h	DTCCR6	DTC Control Register 6	XXh	
06C71h	DTBLS6	DTC Block Size Register 6	XXh	
06C72h	DTCCT6	DTC Transfer Count Register 6	XXh	
06C73h	DTRLD6	DTC Transfer Count Reload Register 6	XXh	
06C74h	DTSAR6	DTC Source Address Register 6	XXXXh	
06C75h				
06C76h	DTDAR6	DTC Destination Address Register 6	XXXXh	
06C77h				
06C78h	DTCCR7	DTC Control Register 7	XXh	
06C79h	DTBLS7	DTC Block Size Register 7	XXh	
06C7Ah	DTCCT7	DTC Transfer Count Register 7	XXh	
06C7Bh	DTRLD7	DTC Transfer Count Reload Register 7	XXh	
06C7Ch	DTSAR7	DTC Source Address Register 7	XXXXh	
06C7Dh				
06C7Eh	DTDAR7	DTC Destination Address Register 7	XXXXh	
06C7Fh				
06C80h	DTCCR8	DTC Control Register 8	XXh	
06C81h	DTBLS8	DTC Block Size Register 8	XXh	
06C82h	DTCCT8	DTC Transfer Count Register 8	XXh	
06C83h	DTRLD8	DTC Transfer Count Reload Register 8	XXh	
06C84h	DTSAR8	DTC Source Address Register 8	XXXXh	
06C85h				
06C86h	DTDAR8	DTC Destination Address Register 8	XXXXh	
06C87h				
06C88h	DTCCR9	DTC Control Register 9	XXh	
06C89h	DTBLS9	DTC Block Size Register 9	XXh	
06C8Ah	DTCCT9	DTC Transfer Count Register 9	XXh	
06C8Bh	DTRLD9	DTC Transfer Count Reload Register 9	XXh	
06C8Ch	DTSAR9	DTC Source Address Register 9	XXXXh	
06C8Dh				
06C8Eh	DTDAR9	DTC Destination Address Register 9	XXXXh	
06C8Fh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.15 SFR Information (15) (1)

Address	Symbol	Register Name	After Reset	Remarks
06C90h	DTCCR10	DTC Control Register 10	XXh	
06C91h	DTBLS10	DTC Block Size Register 10	XXh	
06C92h	DTCCT10	DTC Transfer Count Register 10	XXh	
06C93h	DTRLD10	DTC Transfer Count Reload Register 10	XXh	
06C94h	DTSAR10	DTC Source Address Register 10	XXXXh	
06C95h				
06C96h	DTDAR10	DTC Destination Address Register 10	XXXXh	
06C97h				
06C98h	DTCCR11	DTC Control Register 11	XXh	
06C99h	DTBLS11	DTC Block Size Register 11	XXh	
06C9Ah	DTCCT11	DTC Transfer Count Register 11	XXh	
06C9Bh	DTRLD11	DTC Transfer Count Reload Register 11	XXh	
06C9Ch	DTSAR11	DTC Source Address Register 11	XXXXh	
06C9Dh				
06C9Eh	DTDAR11	DTC Destination Address Register 11	XXXXh	
06C9Fh				
06CA0h	DTCCR12	DTC Control Register 12	XXh	
06CA1h	DTBLS12	DTC Block Size Register 12	XXh	
06CA2h	DTCCT12	DTC Transfer Count Register 12	XXh	
06CA3h	DTRLD12	DTC Transfer Count Reload Register 12	XXh	
06CA4h	DTSAR12	DTC Source Address Register 12	XXXXh	
06CA5h				
06CA6h	DTDAR12	DTC Destination Address Register 12	XXXXh	
06CA7h				
06CA8h	DTCCR13	DTC Control Register 13	XXh	
06CA9h	DTBLS13	DTC Block Size Register 13	XXh	
06CAAh	DTCCT13	DTC Transfer Count Register 13	XXh	
06CABh	DTRLD13	DTC Transfer Count Reload Register 13	XXh	
06CACh	DTSAR13	DTC Source Address Register 13	XXXXh	
06CADh				
06CAEh	DTDAR13	DTC Destination Address Register 13	XXXXh	
06CAFh				
06CB0h	DTCCR14	DTC Control Register 14	XXh	
06CB1h	DTBLS14	DTC Block Size Register 14	XXh	
06CB2h	DTCCT14	DTC Transfer Count Register 14	XXh	
06CB3h	DTRLD14	DTC Transfer Count Reload Register 14	XXh	
06CB4h	DTSAR14	DTC Source Address Register 14	XXXXh	
06CB5h				
06CB6h	DTDAR14	DTC Destination Address Register 14	XXXXh	
06CB7h				
06CB8h	DTCCR15	DTC Control Register 15	XXh	
06CB9h	DTBLS15	DTC Block Size Register 15	XXh	
06CBAh	DTCCT15	DTC Transfer Count Register 15	XXh	
06CBBh	DTRLD15	DTC Transfer Count Reload Register 15	XXh	
06CBCh	DTSAR15	DTC Source Address Register 15	XXXXh	
06CBDh				
06CBEh	DTDAR15	DTC Destination Address Register 15	XXXXh	
06CBFh				
06CC0h	DTCCR16	DTC Control Register 16	XXh	
06CC1h	DTBLS16	DTC Block Size Register 16	XXh	
06CC2h	DTCCT16	DTC Transfer Count Register 16	XXh	
06CC3h	DTRLD16	DTC Transfer Count Reload Register 16	XXh	
06CC4h	DTSAR16	DTC Source Address Register 16	XXXXh	
06CC5h				
06CC6h	DTDAR16	DTC Destination Address Register 16	XXXXh	
06CC7h				
06CC8h	DTCCR17	DTC Control Register 17	XXh	
06CC9h	DTBLS17	DTC Block Size Register 17	XXh	
06CCAh	DTCCT17	DTC Transfer Count Register 17	XXh	
06CCBh	DTRLD17	DTC Transfer Count Reload Register 17	XXh	
06CCCh	DTSAR17	DTC Source Address Register 17	XXXXh	
06CCDh				
06CCEh	DTDAR17	DTC Destination Address Register 17	XXXXh	
06CCFh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.16 SFR Information (16) (1)

Address	Symbol	Register Name	After Reset	Remarks
06CD0h	DTCCR18	DTC Control Register 18	XXh	
06CD1h	DTBLS18	DTC Block Size Register 18	XXh	
06CD2h	DTCCT18	DTC Transfer Count Register 18	XXh	
06CD3h	DTRLD18	DTC Transfer Count Reload Register 18	XXh	
06CD4h	DTSAR18	DTC Source Address Register 18	XXXXh	
06CD5h				
06CD6h	DTDAR18	DTC Destination Address Register 18	XXXXh	
06CD7h				
06CD8h	DTCCR19	DTC Control Register 19	XXh	
06CD9h	DTBLS19	DTC Block Size Register 19	XXh	
06CDAh	DTCCT19	DTC Transfer Count Register 19	XXh	
06CDBh	DTRLD19	DTC Transfer Count Reload Register 19	XXh	
06CDCh	DTSAR19	DTC Source Address Register 19	XXXXh	
06CDDh				
06CDEh	DTDAR19	DTC Destination Address Register 19	XXXXh	
06CDFh				
06CE0h	DTCCR20	DTC Control Register 20	XXh	
06CE1h	DTBLS20	DTC Block Size Register 20	XXh	
06CE2h	DTCCT20	DTC Transfer Count Register 20	XXh	
06CE3h	DTRLD20	DTC Transfer Count Reload Register 20	XXh	
06CE4h	DTSAR20	DTC Source Address Register 20	XXXXh	
06CE5h				
06CE6h	DTDAR20	DTC Destination Address Register 20	XXXXh	
06CE7h				
06CE8h	DTCCR21	DTC Control Register 21	XXh	
06CE9h	DTBLS21	DTC Block Size Register 21	XXh	
06CEAh	DTCCT21	DTC Transfer Count Register 21	XXh	
06CEBh	DTRLD21	DTC Transfer Count Reload Register 21	XXh	
06CECh	DTSAR21	DTC Source Address Register 21	XXXXh	
06CEDh				
06CEEh	DTDAR21	DTC Destination Address Register 21	XXXXh	
06CEFh				
06CF0h	DTCCR22	DTC Control Register 22	XXh	
06CF1h	DTBLS22	DTC Block Size Register 22	XXh	
06CF2h	DTCCT22	DTC Transfer Count Register 22	XXh	
06CF3h	DTRLD22	DTC Transfer Count Reload Register 22	XXh	
06CF4h	DTSAR22	DTC Source Address Register 22	XXXXh	
06CF5h				
06CF6h	DTDAR22	DTC Destination Address Register 22	XXXXh	
06CF7h				
06CF8h	DTCCR23	DTC Control Register 23	XXh	
06CF9h	DTBLS23	DTC Block Size Register 23	XXh	
06CFAh	DTCCT23	DTC Transfer Count Register 23	XXh	
06CFBh	DTRLD23	DTC Transfer Count Reload Register 23	XXh	
06CFCh	DTSAR23	DTC Source Address Register 23	XXXXh	
06CFDh				
06CFEh	DTDAR23	DTC Destination Address Register 23	XXXXh	
06CFFh				
06D00h to 06FFFh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.17 ID code Area, Option Function Select Area

Address	Symbol	Area Name	After Reset	Address size
:				
0FFDBh	OFS2	Option Function Select Register 2	(Note 1)	
:				
0FFDFh	ID1		(Note 2)	
:				
0FFE3h	ID2		(Note 2)	
:				
0FFEBh	ID3		(Note 2)	
:				
0FFEFh	ID4		(Note 2)	
:				
0FFF3h	ID5		(Note 2)	
:				
0FFF7h	ID6		(Note 2)	
:				
0FFFBh	ID7		(Note 2)	
:				
0FFFFh	OFS	Option Function Select Register	(Note 1)	

Notes:
1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not perform any additional writes to the option function select area. Erasing the block including the option function select area sets the option function select area to FFh.
2. The ID code area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not perform any additional writes to the ID code area. Erasing the block including the ID code area sets the ID code area to FFh.

4. Electrical Characteristics

4.1 Absolute Maximum Ratings

Table 4.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
Vcc/AVcc ICEVcc	Supply voltage		–0.3 to 6.5	V
V_I	Input voltage		–0.3 to Vcc + 0.3	V
V_O	Output voltage		–0.3 to Vcc + 0.3	V
P_d	Power dissipation	–40°C ≤ Topr ≤ 85°C	500	mW
T_{opr}	Operating ambient temperature		–20 to 85 (N version)/ –40 to 85 (D version)	°C
T_{stg}	Storage temperature		–65 to 150	°C

4.2 Recommended Operating Conditions

Table 4.2 Recommended Operating Conditions (1)
(Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
V_{CC}/AV_{CC}	Supply voltage					1.8	—	5.5	V
V_{SS}/AV_{SS}	Supply voltage					—	0	—	V
V_{IH}	Input high voltage	Other than CMOS input				0.8V_{CC}	—	V_{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection: 0.35V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0.5V_{CC}	—	V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0.55V_{CC}	—	V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0.65V_{CC}	—	V_{CC}	V
				Input level selection: 0.5V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0.65V_{CC}	—	V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0.7V_{CC}	—	V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0.8V_{CC}	—	V_{CC}	V
				Input level selection: 0.7V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0.85V_{CC}	—	V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0.85V_{CC}	—	V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0.85V_{CC}	—	V_{CC}	V
		External clock input (XOUT)				1.2	—	V_{CC}	V
V_{IL}	Input low voltage	Other than CMOS input				0	—	0.2V_{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection: 0.35V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0	—	0.2V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0	—	0.2V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0	—	0.2V_{CC}	V
				Input level selection: 0.5V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0	—	0.4V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0	—	0.3V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0	—	0.2V_{CC}	V
				Input level selection: 0.7V_{CC}	4.0 V ≤ V_{CC} ≤ 5.5 V	0	—	0.55V_{CC}	V
					2.7 V ≤ V_{CC} < 4.0 V	0	—	0.45V_{CC}	V
					1.8 V ≤ V_{CC} < 2.7 V	0	—	0.35V_{CC}	V
		External clock input (XOUT)				0	—	0.4	V
$I_{OH(sum)}$	Peak sum output high current		Sum of all pins $I_{OH(peak)}$			—	—	–80	mA
$I_{OH(sum)}$	Average sum output high current		Sum of all pins $I_{OH(avg)}$			—	—	–40	mA
$I_{OH(peak)}$	Peak output high current		When drive capacity is low			—	—	–10	mA
			When drive capacity is high			—	—	–40	mA
$I_{OH(avg)}$	Average output high current		When drive capacity is low			—	—	–5	mA
			When drive capacity is high			—	—	–20	mA
$I_{OL(sum)}$	Peak sum output low current		Sum of all pins $I_{OL(peak)}$			—	—	80	mA
$I_{OL(sum)}$	Average sum output low current		Sum of all pins $I_{OL(avg)}$			—	—	40	mA
$I_{OL(peak)}$	Peak output low current		When drive capacity is low			—	—	10	mA
			When drive capacity is high			—	—	40	mA
$I_{OL(avg)}$	Average output low current		When drive capacity is low			—	—	5	mA
			When drive capacity is high			—	—	20	mA
$f_{(XIN)}$	XIN clock input oscillation frequency				2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ V_{CC} < 2.7 V	—	—	5	MHz
$f_{(XCIN)}$	XCIN clock input oscillation frequency				1.8 V ≤ V_{CC} ≤ 5.5 V	—	32.768	50	kHz
fHOCO	Count source for timer RC				2.7 V ≤ V_{CC} ≤ 5.5 V	32	—	40	MHz
fHOCO-F	fHOCO-F frequency				2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ V_{CC} < 2.7 V	—	—	5	MHz
—	System clock frequency				2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ V_{CC} < 2.7 V	—	—	5	MHz
$f_{(BCLK)}$	CPU clock frequency				2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ V_{CC} < 2.7 V	—	—	5	MHz

Note:
1. The average output current indicates the average value of current measured during 100 ms.

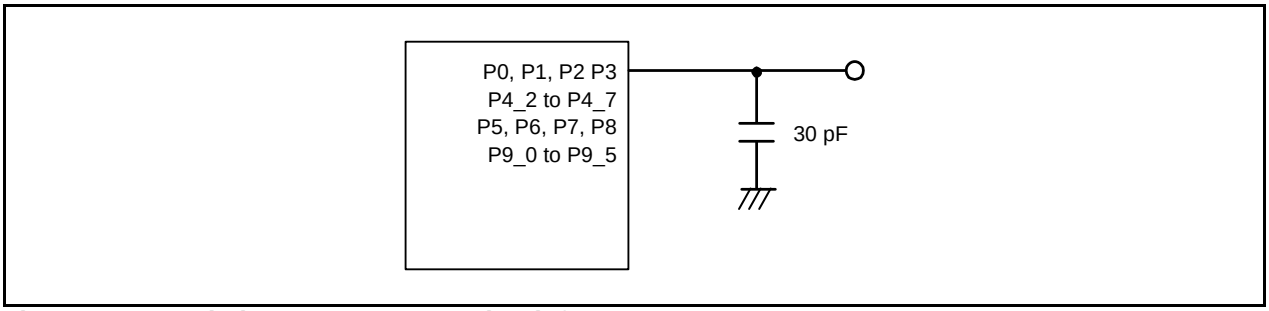


Figure 4.1 Timing Measurement Circuit for Ports P0, P1, P2, P3, P4_2 to P4_7, P5, P6, P7, P8, and P9_0 to P9_5

4.3 Peripheral Function Characteristics

Table 4.3 A/D Converter Characteristics
(Vcc/AVcc = Vref = 2.2 V to 5.5 V, Vss = 0 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
—	Resolution		V_{ref} = AVcc		—	—	10	Bit
—	Absolute accuracy	10-bit mode	V_{ref} = AVcc = 5.0 V	AN0 to AN19 input	—	—	±3	LSB
			V_{ref} = AVcc = 3.3 V	AN0 to AN19 input	—	—	±5	LSB
			V_{ref} = AVcc = 3.0 V	AN0 to AN19 input	—	—	±5	LSB
			V_{ref} = AVcc = 2.2 V	AN0 to AN19 input	—	—	±5	LSB
		8-bit mode	V_{ref} = AVcc = 5.0 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AVcc = 3.3 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AVcc = 3.0 V	AN0 to AN19 input	—	—	±2	LSB
			V_{ref} = AVcc = 2.2 V	AN0 to AN19 input	—	—	±2	LSB
ϕAD	A/D conversion clock		4.0 V ≤ V_{ref} = AVcc ≤ 5.5 V (1)		2	—	20	MHz
			3.2 V ≤ V_{ref} = AVcc ≤ 5.5 V (1)		2	—	16	MHz
			2.7 V ≤ V_{ref} = AVcc ≤ 5.5 V (1)		2	—	10	MHz
			2.2 V ≤ V_{ref} = AVcc ≤ 5.5 V (1)		2	—	5	MHz
—	Tolerance level impedance				—	3	—	kΩ
I_{vref}	Vref current		Vcc = 5 V, XIN = f1 = fAD = 20 MHz		—	45	—	µA
t_{CONV}	Conversion time	10-bit mode	V_{ref} = AVcc = 5.0 V, ϕAD = 20 MHz		2.2	—	—	µs
		8-bit mode	V_{ref} = AVcc = 5.0 V, ϕAD = 20 MHz		2.2	—	—	µs
t_{SAMP}	Sampling time		ϕAD = 20 MHz		0.8	—	—	µs
V_{ref}	Reference voltage				2.2	—	AVcc	V
V_{IA}	Analog input voltage (2)				0	—	V_{ref}	V
OCVREF	On-chip reference voltage		2MHz ≤ ϕAD ≤ 4MHz		1.19	1.34	1.49	V

Notes:
1. If the CPU and the flash memory stop, the A/D conversion result will be undefined.
2. When the analog input voltage exceeds the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 4.4 Comparator B Characteristics
(Vcc/AVcc = 2.2 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{ref}	IVREF1, IVREF3 input reference voltage		0	—	Vcc – 1.4	V
V_I	IVCMP1, IVCMP3 input voltage		–0.3	—	Vcc + 0.3	V
—	Offset		—	5	100	mV
t_d	Comparator output delay time (1)	V_I = V_{ref} ±100 mV	—	0.1	—	µs
I_{CMP}	Comparator operating current	Vcc = 5.0 V	—	17.5	—	µA

Note:
1. When the digital filter is not selected.

Table 4.5 Flash Memory (Program ROM) Characteristics (Vcc = 2.7 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		1,000 (2)	—	—	times
—	Byte program time (Program and erase endurance ≤ 100 times)		—	—	—	µs
—	Byte program time (Program and erase endurance ≤ 1,000 times)		—	—	—	µs
—	Word program time (Program and erase endurance ≤ 100 times)	Topr = 25°C, Vcc = 5.0 V	—	100	200	µs
—	Word program time (Program and erase endurance ≤ 100 times)		—	100	400	µs
—	Word program time (Program and erase endurance ≤ 1,000 times)		—	100	650	µs
—	Block erase time		—	0.3	4	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		–20 (N ver.) –40 (D ver.)	—	85	°C
—	Data hold time (6)	Ambient temperature = 55°C (7)	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 100 or 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. The data hold time includes 7,000 hours under an environment of ambient temperature 85°C.

Table 4.6 Flash Memory (Data flash Block A to Block D) Characteristics (Vcc = 2.7 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		10,000 (2)	—	—	times
—	Byte program time (Program and erase endurance ≤ 1,000 times)		—	160	950	µs
—	Byte program time (Program and erase endurance > 1,000 times)		—	300	950	µs
—	Block erase time (Program and erase endurance ≤ 1,000 times)		—	0.2	1	s
—	Block erase time (Program and erase endurance > 1,000 times)		—	0.3	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	3 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		–20 (N ver.) –40 (D ver.)	—	85	°C
—	Data hold time (6)	Ambient temperature = 55°C (7)	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 100, 1,000 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. The data hold time includes 7,000 hours under an environment of ambient temperature 85°C.

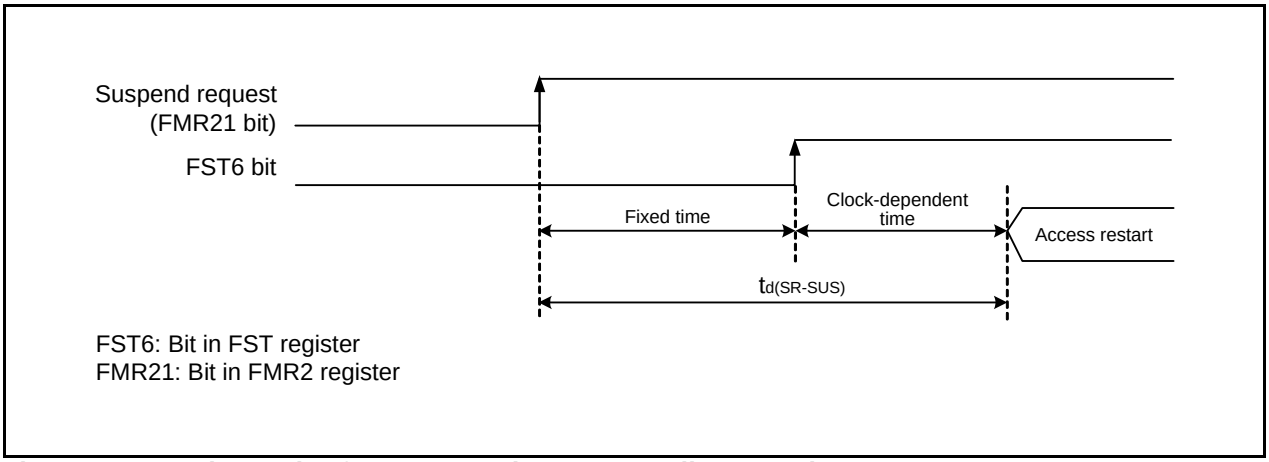


Figure 4.2 Time Delay from Suspend Request until Suspend

Table 4.7 Voltage Detection 0 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det0}	Voltage detection level Vdet0_0 (1)	When Vcc falls	1.80	1.90	2.05	V
	Voltage detection level Vdet0_1 (1)	When Vcc falls	2.15	2.35	2.55	V
	Voltage detection level Vdet0_2 (1)	When Vcc falls	2.70	2.85	3.05	V
	Voltage detection level Vdet0_3 (1)	When Vcc falls	3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet0 – 0.1) V	—	6	150	µs
—	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	—	1.5	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. The voltage detection level must be selected with bits VDSEL0 and VDSEL1 in the OFS register.
2. Time until the voltage monitor 0 reset is generated after the voltage passes V_{det0}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.

Table 4.8 Voltage Detection 1 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level Vdet1_0 (1)	When Vcc falls	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 (1)	When Vcc falls	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 (1)	When Vcc falls	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 (1)	When Vcc falls	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 (1)	When Vcc falls	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 (1)	When Vcc falls	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 (1)	When Vcc falls	2.80	3.10	3.40	V
	Voltage detection level Vdet1_7 (1)	When Vcc falls	2.95	3.25	3.55	V
	Voltage detection level Vdet1_8 (1)	When Vcc falls	3.10	3.40	3.70	V
	Voltage detection level Vdet1_9 (1)	When Vcc falls	3.25	3.55	3.85	V
	Voltage detection level Vdet1_A (1)	When Vcc falls	3.40	3.70	4.00	V
	Voltage detection level Vdet1_B (1)	When Vcc falls	3.55	3.85	4.15	V
	Voltage detection level Vdet1_C (1)	When Vcc falls	3.70	4.00	4.30	V
	Voltage detection level Vdet1_D (1)	When Vcc falls	3.85	4.15	4.45	V
	Voltage detection level Vdet1_E (1)	When Vcc falls	4.00	4.30	4.60	V
	Voltage detection level Vdet1_F (1)	When Vcc falls	4.15	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet1 – 0.1) V	—	60	150	µs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 4.9 Voltage Detection 2 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

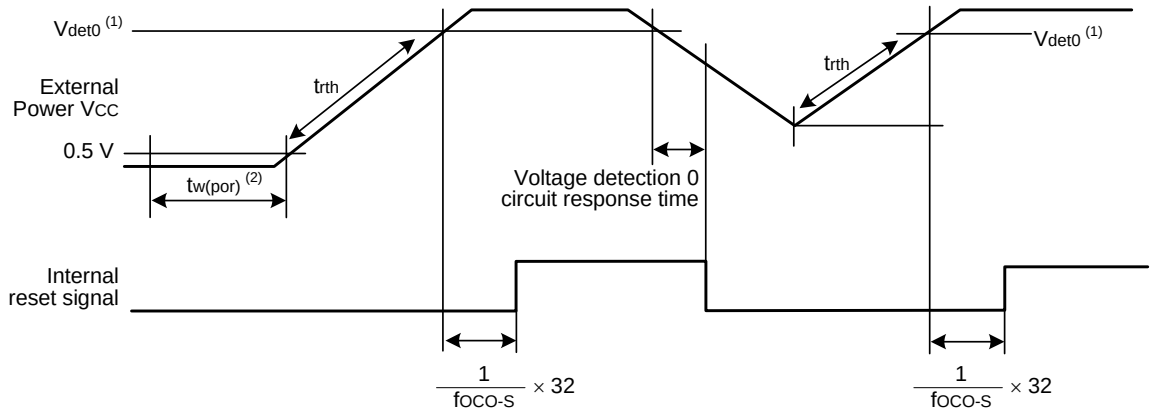
Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0	When Vcc falls	3.70	4.00	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		—	0.1	—	µs
—	Voltage detection 2 circuit response time (1)	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	µs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (2)		—	—	100	µs

Notes:
1. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 4.10 Power-On Reset Circuit Characteristics (1)
(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{rth}	External power VCC rise gradient		0	—	50,000	mV/msec

Note:
1. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.



Notes:
1. V_{det0} indicates the voltage detection level of the voltage detection 0 circuit. Refer to the **Voltage Detection Circuit** chapter of User's Manual: Hardware for details.
2. $t_{w(por)}$ indicates the duration the external power Vcc must be held below the valid voltage (0.5 V) to enable a power-on reset. When turning on the power after it falls with voltage monitor 0 reset disabled, maintain $t_{w(por)}$ for 1 ms or more.

Figure 4.3 Power-on Reset Circuit Characteristics

Table 4.11 High-Speed On-Chip Oscillator Circuit Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	High-speed on-chip oscillator frequency after reset	Vcc = 1.8 V to 5.5 V, –20°C ≤ Topr ≤ 85°C (N version) –40°C ≤ Topr ≤ 85°C (D version)	—	40	—	MHz
	High-speed on-chip oscillator frequency when 01b or 10b is written to bits FRA25 and FRA24 in the FRA2 register (1)		—	36.864	—	MHz
	High-speed on-chip oscillator frequency when 10b is written to bits FRA25 and FRA24 in the FRA2 register		—	32	—	MHz
	High-speed on-chip oscillator frequency dependence on temperature and power supply voltage (2)		– 1.5	—	1.5	%
—	Oscillation stability time	Vcc = 5.0 V, Topr = 25°C	—	250	—	µs
—	Self power consumption at oscillation	Vcc = 5.0 V, Topr = 25°C	—	500	—	µA

Notes:
1. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.
2. This indicates the precision error for the oscillation frequency of the high-speed on-chip oscillator.

Table 4.12 Low-Speed On-Chip Oscillator Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
fLOCO	Low-speed on-chip oscillator frequency		60	125	250	kHz
—	Oscillation stability time	Vcc = 5.0 V, Topr = 25°C	—	30	100	µs
—	Self power consumption at oscillation	Vcc = 5.0 V, Topr = 25°C	—	3	—	µA

Table 4.13 Power Supply Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during power-on (1)		—	—	2,000	µs

Note:
1. Waiting time until the internal power supply generation circuit stabilizes during power-on.

4.4 DC Characteristics

Table 4.14 DC Characteristics (1) [4.2 V ≤ Vcc ≤ 5.5 V] (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –20 mA	Vcc – 2.0	—	Vcc	V
			Drive capacity is low	I_{OH} = –5 mA	Vcc – 2.0	—	Vcc	V
				I_{OH} = –200 µA	Vcc – 0.3	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL}= 20 mA	—	—	2.0	V
			Drive capacity is low	I_{OL} = 5 mA	—	—	2.0	V
				I_{OL} = 200 µA	—	—	0.45	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, $\overline{RXD\_0}$, RXD_1, $\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\underline{SCL\_0}$, SDA_0, SSI_0, $\overline{SCS\_0}$, SSCK_0, SSO_0			0.1	1.2	—	V
		$\overline{RESET}$	Vcc = 5.0 V		0.1	1.2	—	V
I_{IH}	Input high current		V_I = 5.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		25	50	100	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.15 DC Characteristics (2) [3.3 V ≤ Vcc ≤ 5.5 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	6.5	15	mA
			16 MHz	Off	Off	125 kHz	No division	—		—	5.3	12.5	mA
			10 MHz	Off	Off	125 kHz	No division	—		—	3.6	—	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	3.0	—	mA
			16 MHz	Off	Off	125 kHz	Divide-by-8	—		—	2.2	—	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz (3)	125 kHz	No division	—		—	7.0	15	mA
			Off	Off	20 MHz (3)	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	400	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	—	FMR27 = 1 SVC0 = 0		—	85	400	µA
			Off	32 kHz	Off	Off	—	FMSTP = 1 SVC0 = 0	Program operation on RAM Flash memory off	—	47	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	100	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	90	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 3.3 V to 5.5 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Table 4.16 DC Characteristics (3) [2.7 V ≤ Vcc < 4.2 V] (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –5 mA	Vcc – 0.5	—	Vcc	V
			Drive capacity is low	I_{OH} = –1 mA	Vcc – 0.5	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL} = 5 mA	—	—	0.5	V
			Drive capacity is low	I_{OL} = 1 mA	—	—	0.5	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, RXD_0, RXD_1, $\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\underline{SCL\_0}$, SDA_0, SSI_0, $\overline{SCS\_0}$, SSCK_0, SSO_0			0.1	0.4	—	V
		$\overline{RESET}$	Vcc = 3.0 V		0.1	0.5	—	V
I_{IH}	Input high current		V_I = 3.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		42	84	168	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.17 DC Characteristics (4) [2.7 V ≤ Vcc < 3.3 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified))

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	10 MHz	Off	Off	125 kHz	No division	—		—	3.5	10	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	7.5	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz (3)	125 kHz	No division	—		—	7.0	15	mA
			Off	Off	20 MHz (3)	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	10 MHz (3)	125 kHz	No division	—		—	4.0	—	mA
			Off	Off	10 MHz (3)	125 kHz	Divide-by-8	—		—	1.5	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	390	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0		—	80	400	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 SVC0 = 0	Program operation on RAM Flash memory off	—	40	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 2.7 V to 3.3 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Table 4.18 DC Characteristics (5) [1.8 V ≤ Vcc < 2.7 V]
(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –2 mA	Vcc – 0.5	—	Vcc	V
			Drive capacity is low	I_{OH} = –1 mA	Vcc – 0.5	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL} = 2 mA	—	—	0.5	V
			Drive capacity is low	I_{OL} = 1 mA	—	—	0.5	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, $\overline{RXD\_0}$, RXD_1,$\overline{CTS2}$, SCL2, SDA2, CLK2, RXD2, $\overline{SCL\_0}$, SDA_0,SSI_0, $\overline{SCS\_0}$, SSCK_0,SSO_0			0.05	0.2	—	V
		$\overline{RESET}$	V_{CC} = 2.2 V		0.05	0.2	—	V
I_{IH}	Input high current		V_I = 2.2 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		100	200	400	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.19 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—		—	2.2	—	mA
			5 MHz	Off	Off	125 kHz	Divide-by-8	—		—	0.8	—	mA
		High-speed on-chip oscillator mode	Off	Off	5 MHz (3)	125 kHz	No division	—		—	2.5	10	mA
			Off	Off	5 MHz (3)	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	300	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0		—	80	350	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 1.8 V to 2.7 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

4.5 AC Characteristics

Table 4.20 Timing Requirements of Clock Synchronous Serial I/O with Chip Select (during Master Operation) (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time		4.00	—	—	t_{CYC} (1)
t_{HI}	SSCK clock high width		0.40	—	0.60	t_{SUCYC}
t_{LO}	SSCK clock low width		0.40	—	0.60	t_{SUCYC}
t_{RISE}	SSCK clock rising time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	0.50	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)
t_{FALL}	SSCK clock falling time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	0.50	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)
t_{SU}	SSI, SSO data input setup time	4.5 V ≤ Vcc ≤ 5.5 V	60	—	—	ns
		2.7 V ≤ Vcc < 4.5 V	70	—	—	ns
		1.8 V ≤ Vcc < 2.7 V	100	—	—	ns
t_H	SSI, SSO data input hold time	2.7 V ≤ Vcc ≤ 5.5 V	2.00	—	—	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	2.00	—	—	t_{CYC} (1)
t_{LEAD}	$\overline{SCS}$-SCK output delay time		0.5 t_{SUCYC} - 1 t_{CYC}	—	—	ns
t_{LAG}	SCK -$\overline{SCS}$ output valid time		0.5 t_{SUCYC} - 1 t_{CYC}	—	—	ns
t_{OD}	SSO data output delay time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	30.00	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)

Note:
1. 1t_{CYC} = 1/f1 (s)

Table 4.21 Timing Requirements of Clock Synchronous Serial I/O with Chip Select (during Slave Operation) (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time		4.00	—	—	t_{CYC} (1)
t_{HI}	SSCK clock high width		0.40	—	0.60	t_{SUCYC}
t_{LO}	SSCK clock low width		0.40	—	0.60	t_{SUCYC}
t_{RISE}	SSCK clock rising time		—	—	1.00	µs
t_{FALL}	SSCK clock falling time		—	—	1.00	µs
t_{SU}	SSO data input setup time		10.00	—	—	ns
t_{H}	SSO data input hold time		2.00	—	—	t_{CYC} (1)
t_{LEAD}	$\overline{SCS}$ setup time		1t_{CYC} + 50	—	—	ns
t_{LAG}	$\overline{SCS}$ hold time		1t_{CYC} + 50	—	—	ns
t_{OD}	SSI, SSO data output delay time	4.5 V ≤ Vcc ≤ 5.5 V	—	—	60	ns
		2.7 V ≤ Vcc < 4.5 V	—	—	70	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	100.00	ns
t_{SA}	SSI slave access time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	1.5t_{CYC} + 100	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	1.5t_{CYC} + 200	ns
t_{OR}	SSI slave out open time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	1.5t_{CYC} + 100	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	1.5t_{CYC} + 200	ns

Note:
1. 1t_{CYC} = 1/f1 (s)

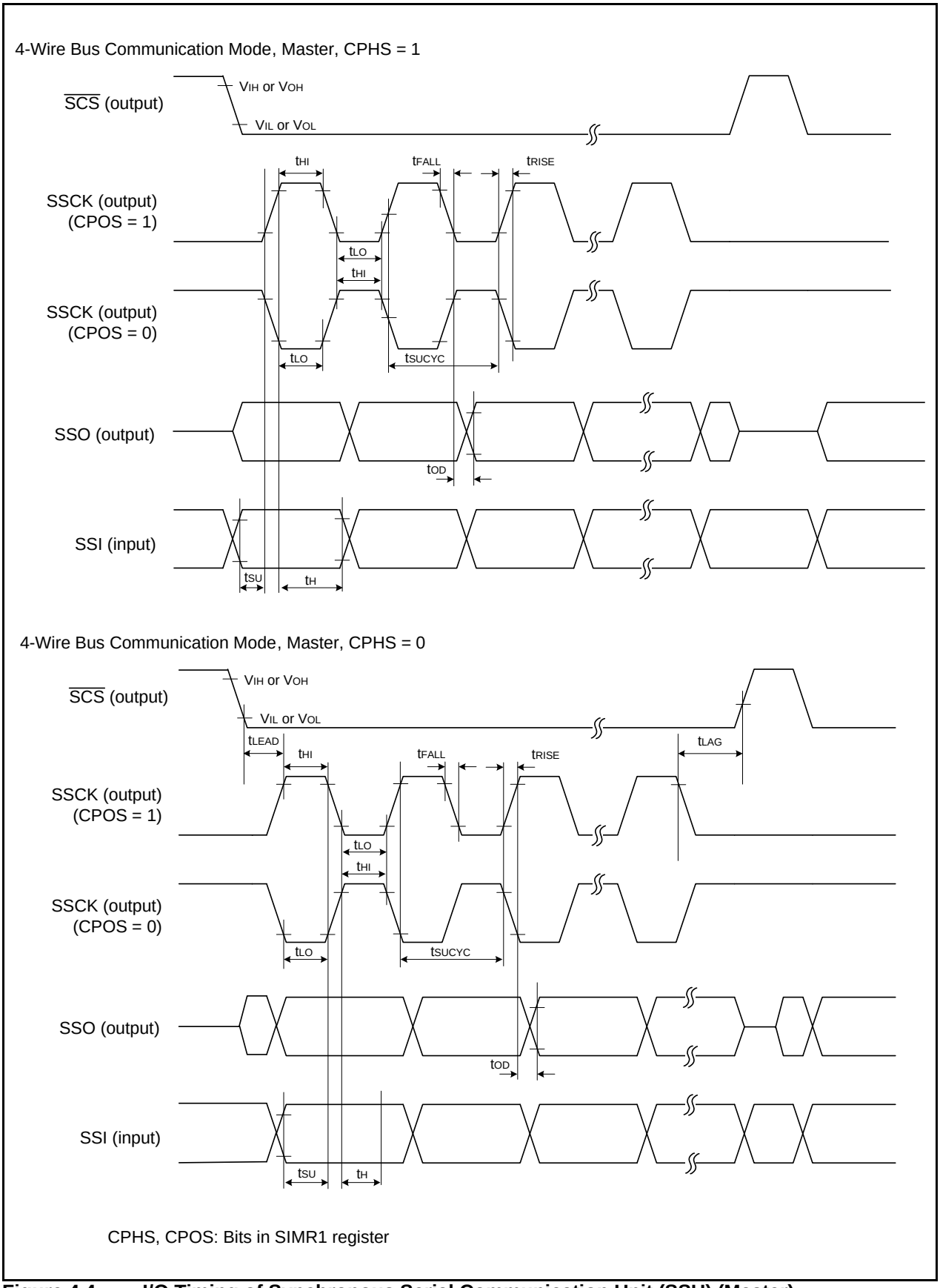


Figure 4.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

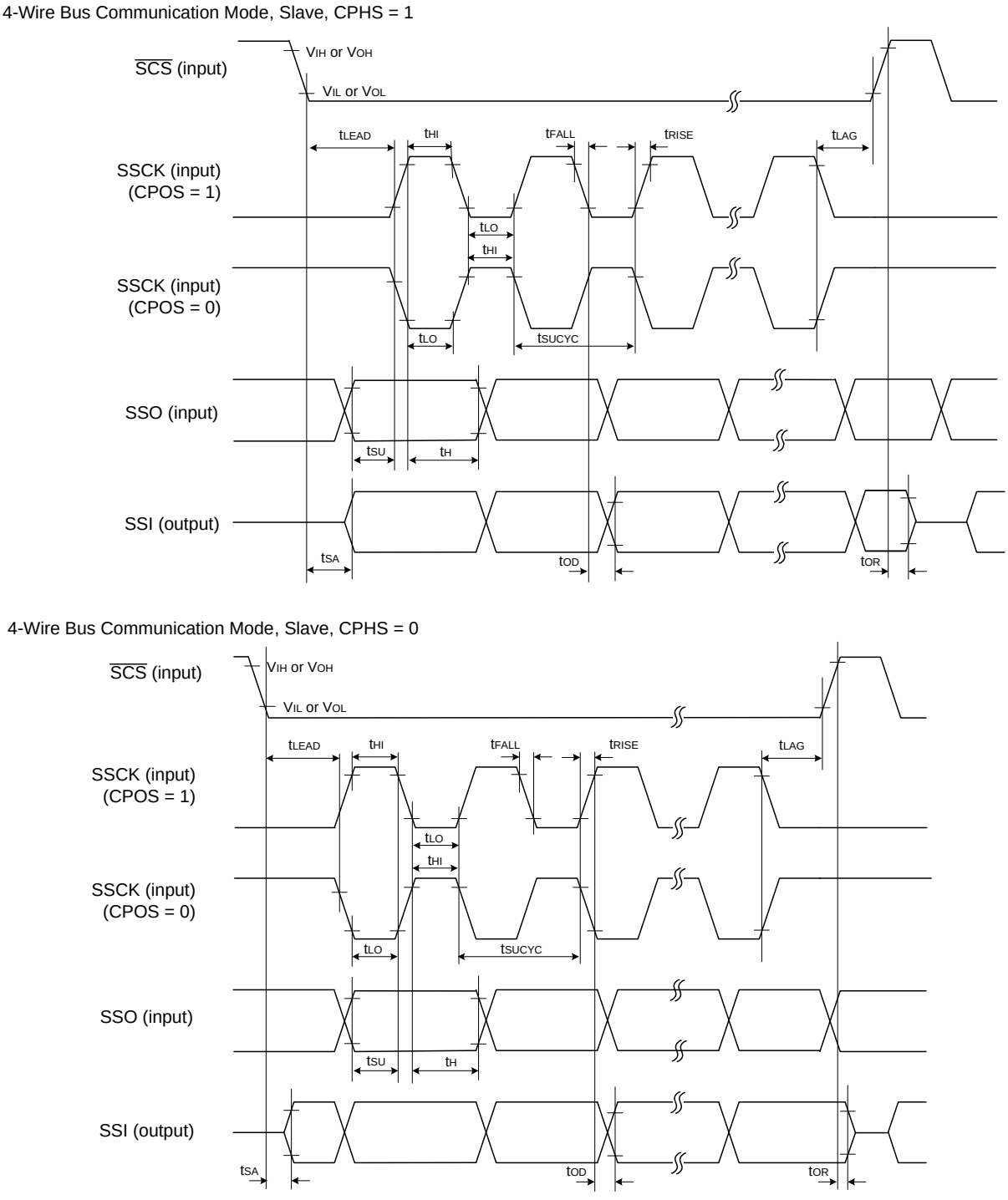


Figure 4.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

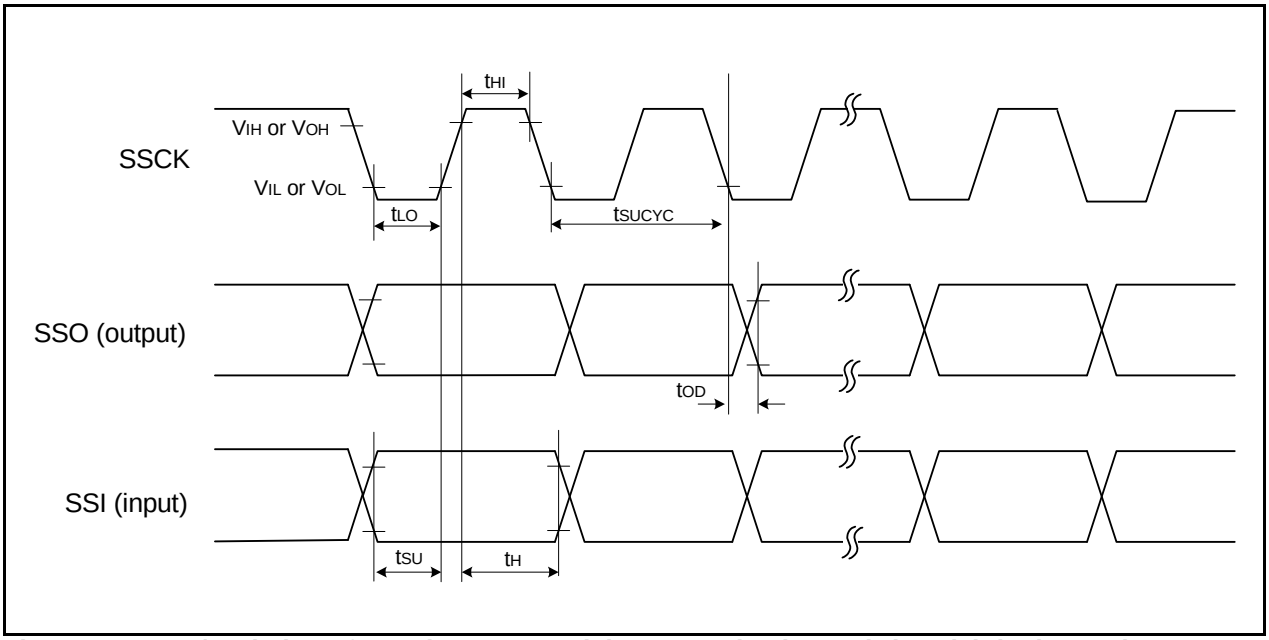


Figure 4.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

Table 4.22 External Clock Input (XOUT, XCIN)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	—	50	—	50	—	ns
$t_{WH(XOUT)}$	XOUT input high width	90	—	24	—	24	—	ns
$t_{WL(XOUT)}$	XOUT input low width	90	—	24	—	24	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	14	—	14	—	µs
$t_{WH(XCIN)}$	XCIN input high width	7	—	7	—	7	—	µs
$t_{WL(XCIN)}$	XCIN input low width	7	—	7	—	7	—	µs

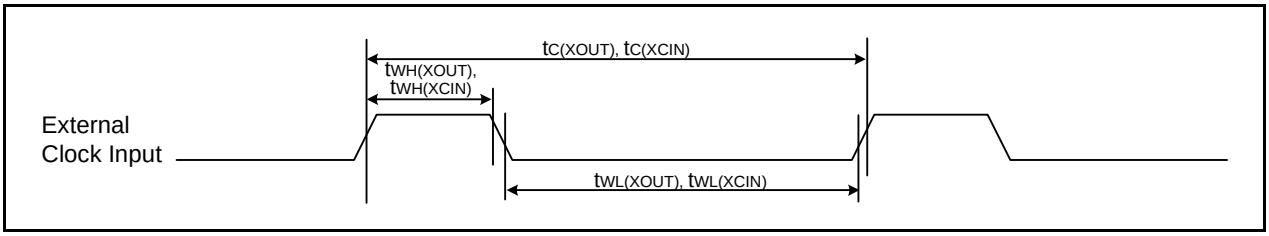


Figure 4.7 External Clock Input Timing Diagram

Table 4.23 Timing Requirements of TRJIO

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(TRJIO)}$	TRJIO input cycle time	500	—	300	—	100	—	ns
$t_{WH(TRJIO)}$	TRJIO input high width	200	—	120	—	40	—	ns
$t_{WL(TRJIO)}$	TRJIO input low width	200	—	120	—	40	—	ns

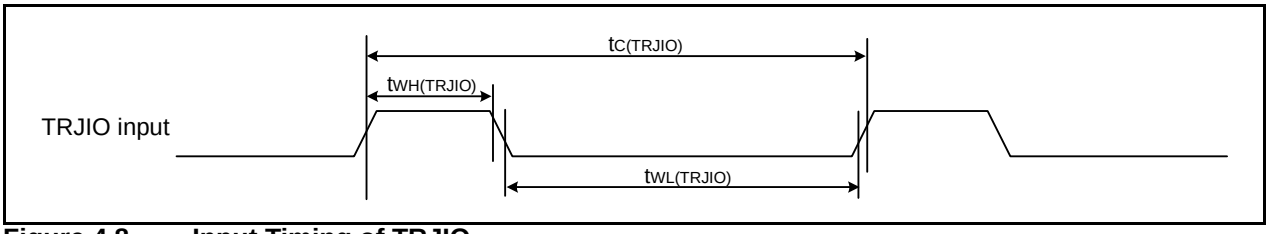


Figure 4.8 Input Timing of TRJIO

Table 4.24 Timing Requirements of Serial Interface (Internal clock selected as transfer clock (master communication))

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{d(C-Q)}$	TXDi output delay time	—	200	—	30	—	10	ns
$t_{su(D-C)}$	RXDi input setup time (1)	150	—	120	—	90	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	90	—	90	—	ns

i = 0 or 1

Note:

1. External pin load condition CL = 30 pF

Table 4.25 Timing Requirements of Serial Interface (External clock selected as transfer clock (slave communication))

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	300	—	200	—	ns
$t_{w(CKH)}$	CLKi input high width	400	—	150	—	100	—	ns
$t_{w(CKL)}$	CLKi input low width	400	—	150	—	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	—	120	—	90	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	30	—	10	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	90	—	90	—	ns

i = 0 or 1

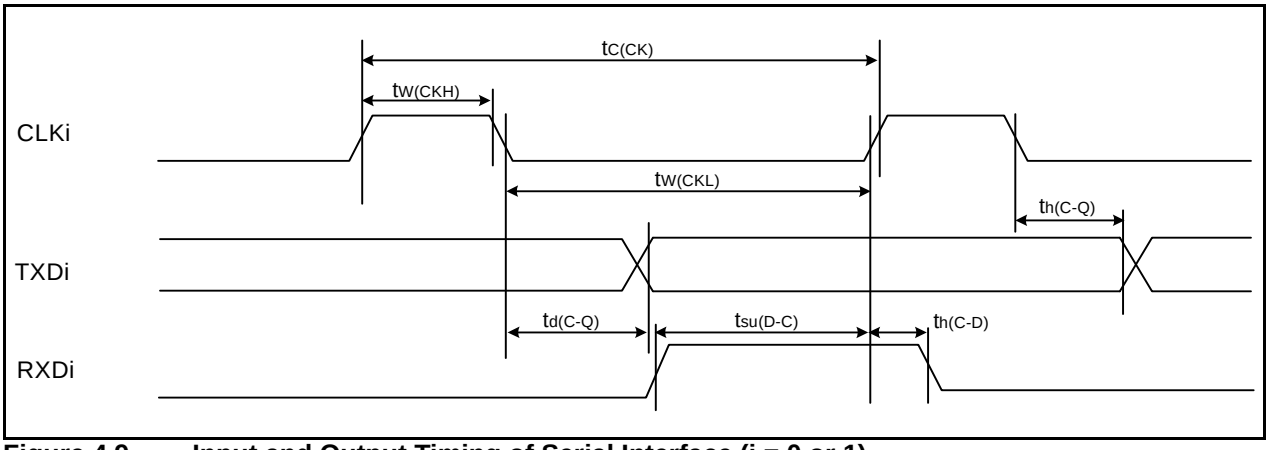


Figure 4.9 Input and Output Timing of Serial Interface (i = 0 or 1)

Table 4.26 Timing Requirements of External Interrupt $\overline{INTi}$ (i = 0 to 4) and Key Input Interrupt $\overline{KIj}$ (j = 0 to 3)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{W(INH)}$	$\overline{INTi}$ input high width, $\overline{KIj}$ input high width	1000 (1)	—	380 (1)	—	250 (1)	—	ns
$t_{W(INL)}$	$\overline{INTi}$ input low width, $\overline{KIj}$ input low width	1000 (2)	—	380 (2)	—	250 (2)	—	ns

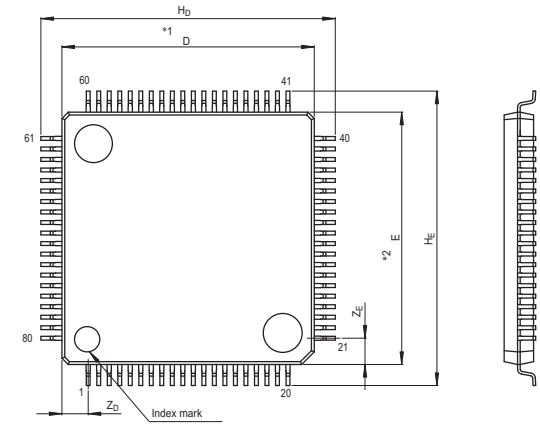
Notes:
1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input high pulse width of either (1/digital filter sampling frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input low pulse width of either (1/digital filter sampling frequency × 3) or the minimum value of standard, whichever is greater.

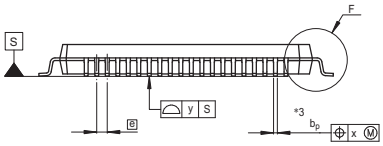
Figure 4.10 Input Timing of External Interrupt $\overline{INTi}$ and Key Input Interrupt $\overline{KIj}$ (i = 0 to 4; j = 0 to 3)

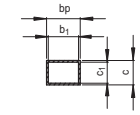
Appendix 1. Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Electronics website.

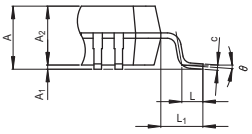
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP80-12x12-0.50	PLQP0080KB-A	80P6Q-A	0.5g







Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	11.9	12.0	12.1
E	11.9	12.0	12.1
A_2	—	1.4	—
H_D	13.8	14.0	14.2
H_E	13.8	14.0	14.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	10°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.25	—
Z_E	—	1.25	—
L	0.3	0.5	0.7
L_1	—	1.0	—

REVISION HISTORY	R8C/38T-A Group User's Manual: Datasheet

Rev.	Date	Description	
		Page	Summary
0.01	Feb 23, 2011	—	First Edition issued
1.00	Dec 09, 2011	All pages	"Preliminary", "Under development" deleted, "sensor control unit" → "touch sensor control unit"
		2, 3	Tables 1.1 and 1.2 revised
		6	Figure 1.3 revised
		16	2.1 revised
		19, 20, 22 to 25, 27 to31	Tables 3.1, 3.2, 3.4 to 3.7, 3.9 to 3.13
		35	Table 3.17 revised, Note 2 added
		36 to 59	"4. Electrical Characteristics" added

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.
   - "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.
   - "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.
   - "Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

RENESAS

SALES OFFICES Renesas Electronics Corporation http://www.renesas.com

Refer to "http://www.renesas.com/" for the latest and detailed information.

Renesas Electronics America Inc.
2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited
1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited
Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.
13F, No. 363, Fu Shing North Road, Taipei, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
1 harbourFront Avenue, #06-10, keppel Bay Tower, Singapore 098632
Tel: +65-6213-0200, Fax: +65-6278-8001

Renesas Electronics Malaysia Sdn.Bhd.
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.
11F., Samik Lavied' or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141

Colophon 1.1